

Encouraging Innovation: The Policies and Partnerships Needed to Support Semiconductor Startups

- Semiconductor startup and investment landscape in 2024 -

Daniel Armbrust

SIA Webinar

– April 4, 2024 –

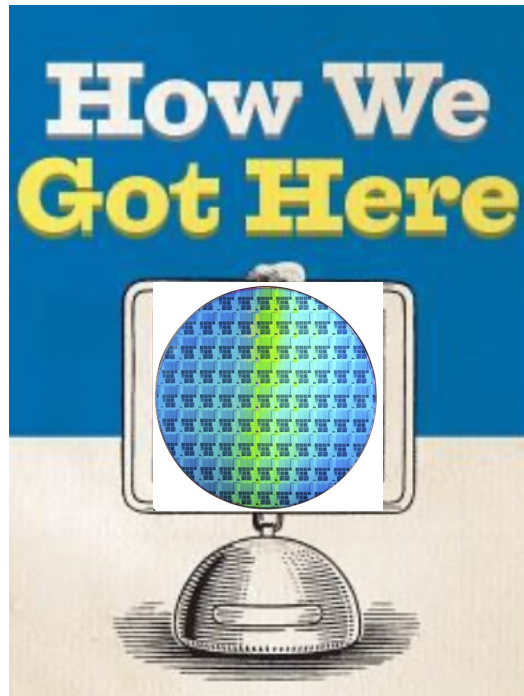
Encouraging Innovation: The Policies and Partnerships Needed to Support Semiconductor Startups

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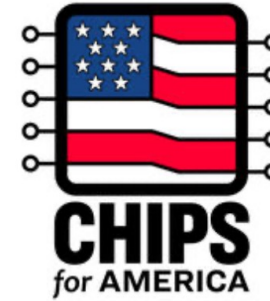
Daniel Armbrust

Remarks today are made in his personal capacity, and his remarks should not be attributed to the Department of Commerce, the Industrial Advisory Committee of the CHIPS Act, or the US Government.

Semiconductor startups and investments



BEHIND THE
STARTUP

A stack of US dollar bills is positioned behind the word "STARTUP".

Recommendations
Policy and
Partnerships



Bottom line up front (BLUF)

Semiconductors are resurgent

Company valuations and profitability

- 8 of the top 20 market caps in tech
- 3rd most profitable industry

AI is profoundly hardware limited -- it's the next gold rush

Essential assets in a geopolitical sea change away from globalism

A surge of investments are underway

CHIPS Act(s) in various countries and regions

VCs are wading back in as there are green shoots in Deep Tech and specialty funds – A contrarian opportunity

Reasonable M&A and IPO opportunities for startups

Chiplets and advanced packaging can advantage startups

Semiconductor startups face daunting challenges

Escalating cost of innovation: prototyping access and costs

Sustained decline of venture capital for semiconductors

Achieving product-market fit remains challenging

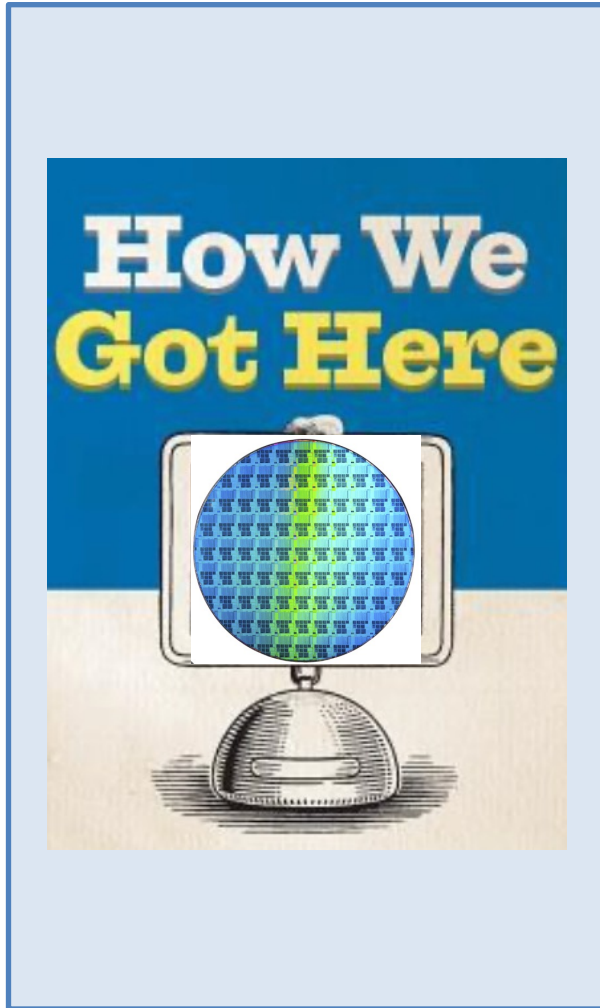
Diminished customer appetite to award design wins to startups

But more research will not lead to commercialization unless we continue to build the startup playbook

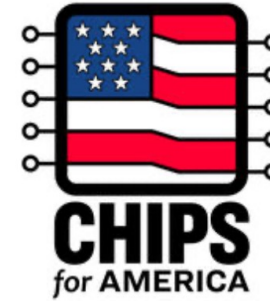
Aggressively implement CHIPS Act investments for prototyping and startup funds with a sense of urgency

Supplement with existing government programs and funding streams

Strengthen startup ecosystem for translation to industry



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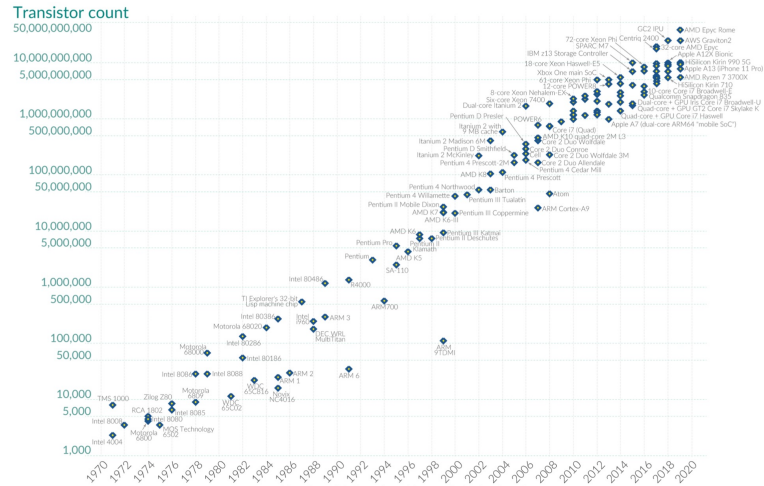


How did we get here?

- 1950's – Invention of the transistor by Bell Labs and dissemination through licensing core technology
- 1960's – Integrated circuits driven by gov't needs, invention of venture capital and startups in Silicon Valley
- 1970's – Invention of microprocessors and DRAM memory
- 1980's – Japanese DRAM threat leads to formation of SIA / SRC / SEMATECH to restore US competitiveness
- 1990's – Foundry business model lead by TSMC in Taiwan
- 2000's – Beginning of industry consolidation; decline in venture capital investment
- 2010's – Moore's Law slowdown, the rise of AI, and emergence of a Chinese threat, pricing power
- 2020's – Pandemic chips shortages, CHIPS Act(s), China's access restrictions, Generative AI

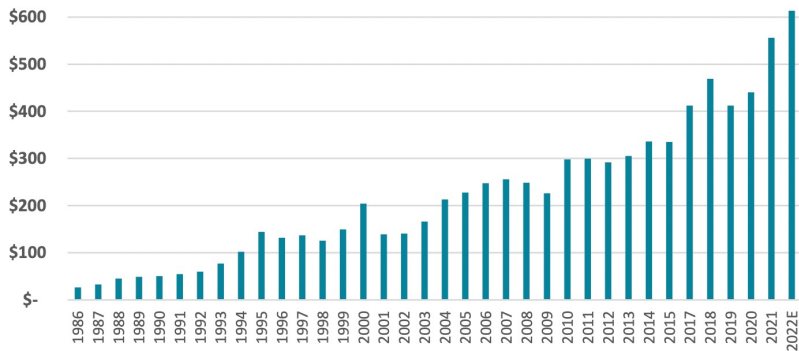
Moore's Law economic-based prediction

Transistors on a Chip



Source: Wikipedia

Semiconductor Revenue



Source: WSTS

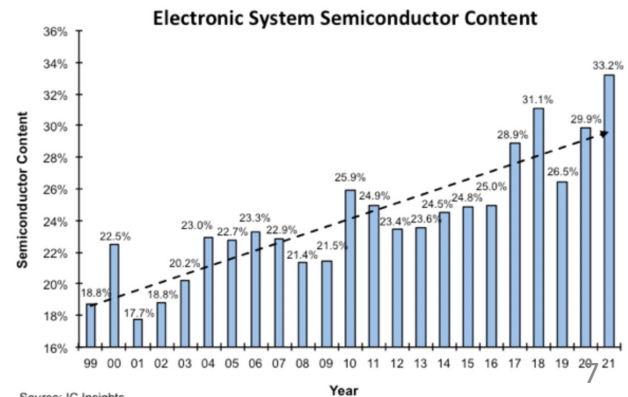
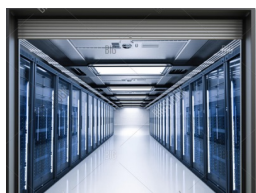
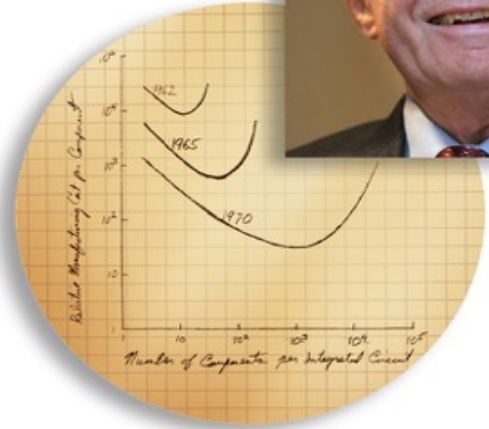
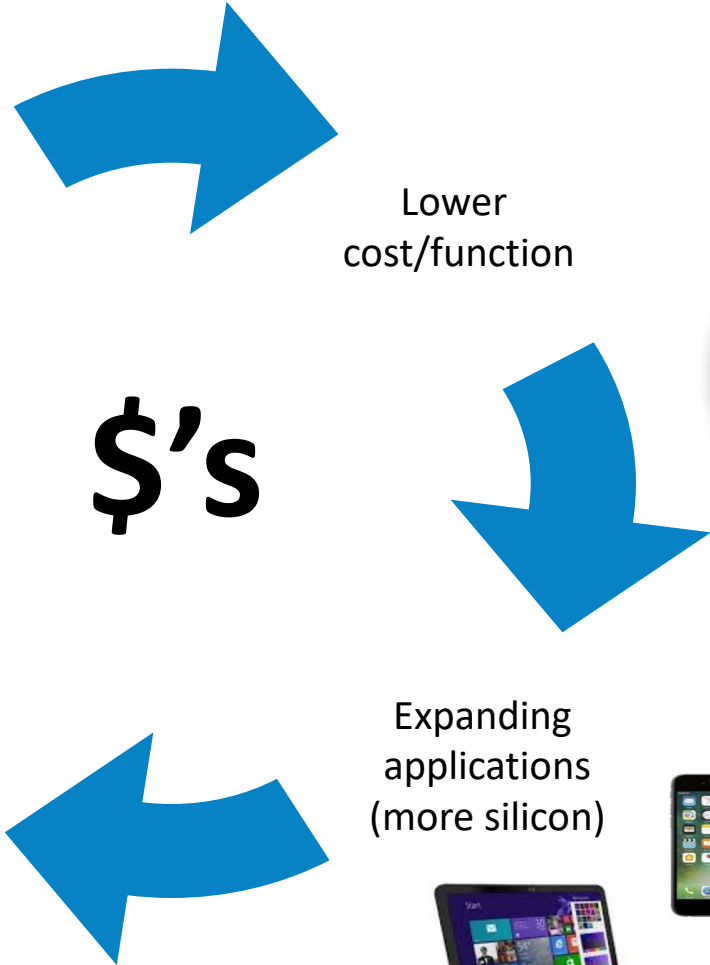
More R&D
(innovation)

Lower cost/function

\$'s

Increasing semiconductor revenue

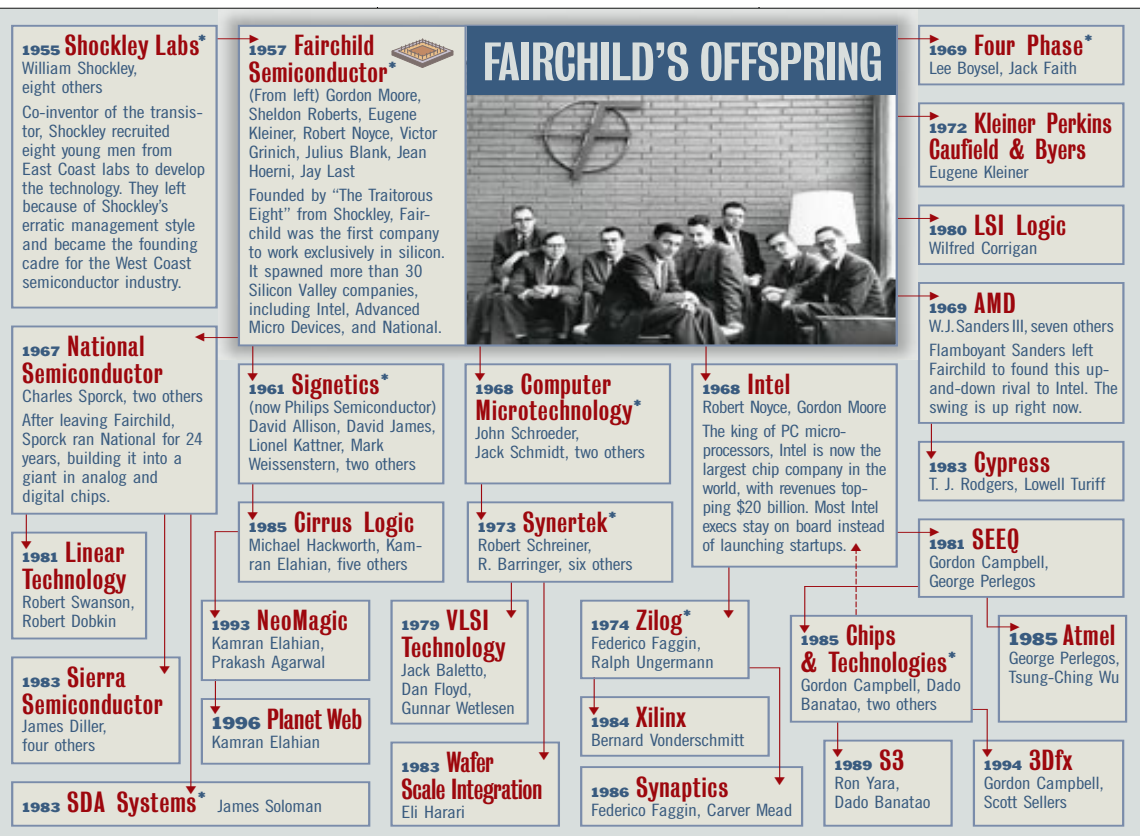
Expanding applications (more silicon)



Source: IC Insights

From U.S. startups and venture capital to geographic dispersion and consolidation

Country Market share (IC Insights)



1960's

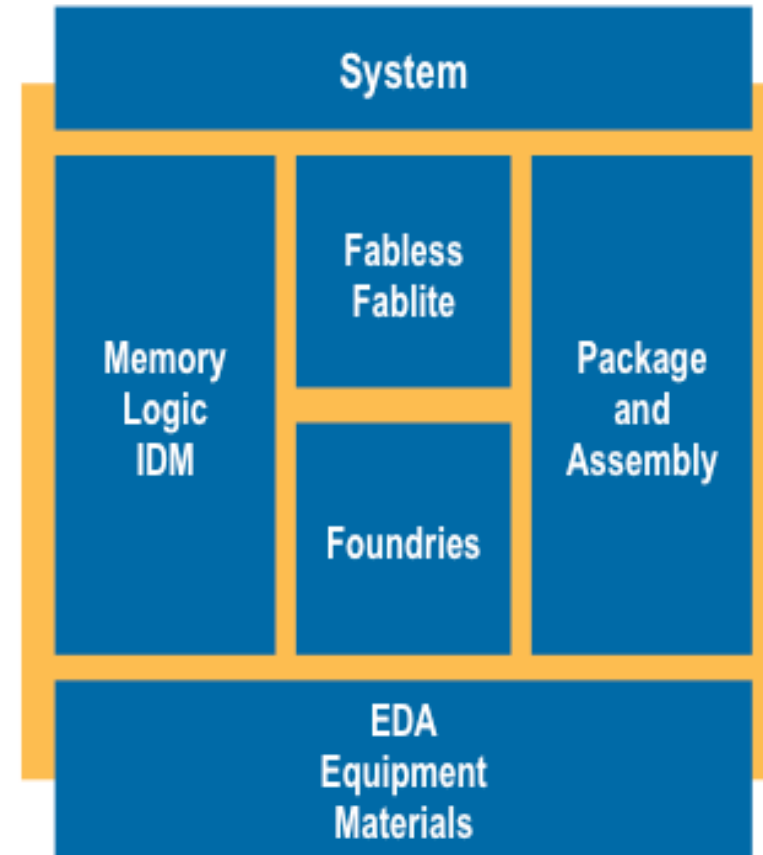
2020's

Evolution of the supply chain and it's fragmentation

historical

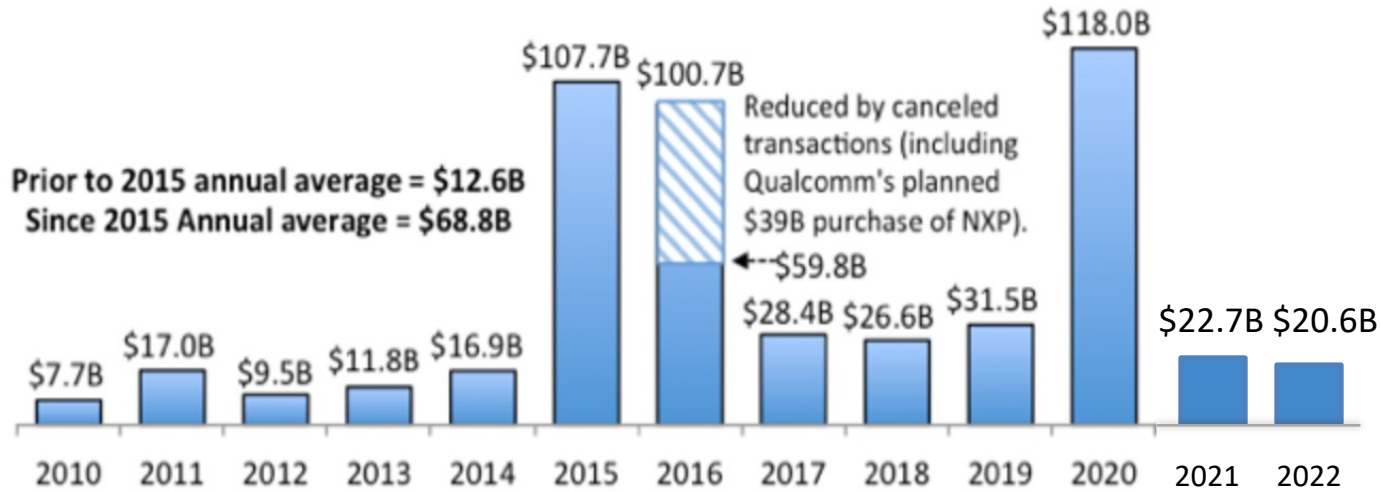


now



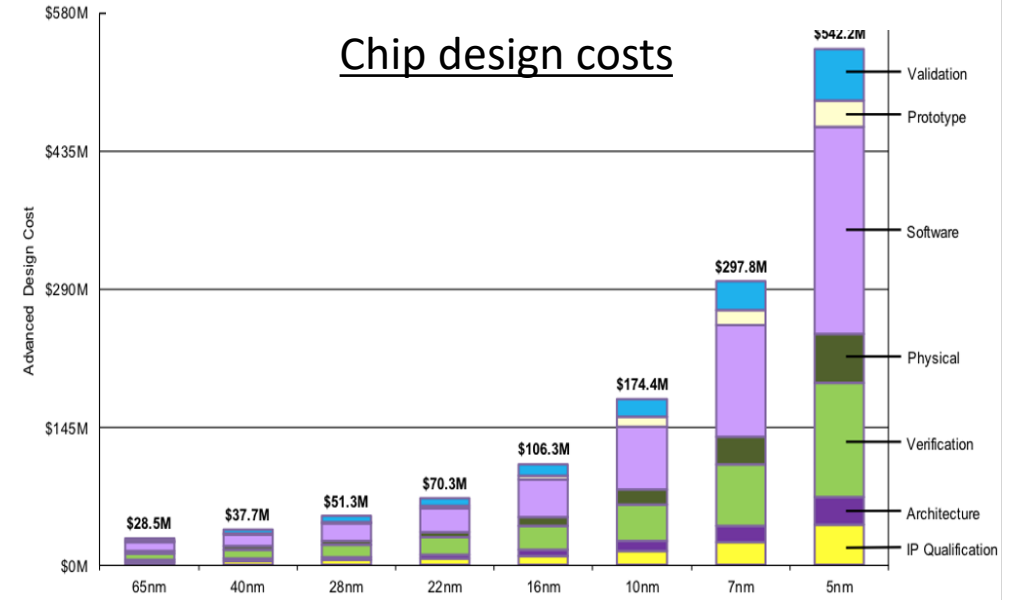
Consolidation and concentration in each segment

Semiconductor M&A Valuation



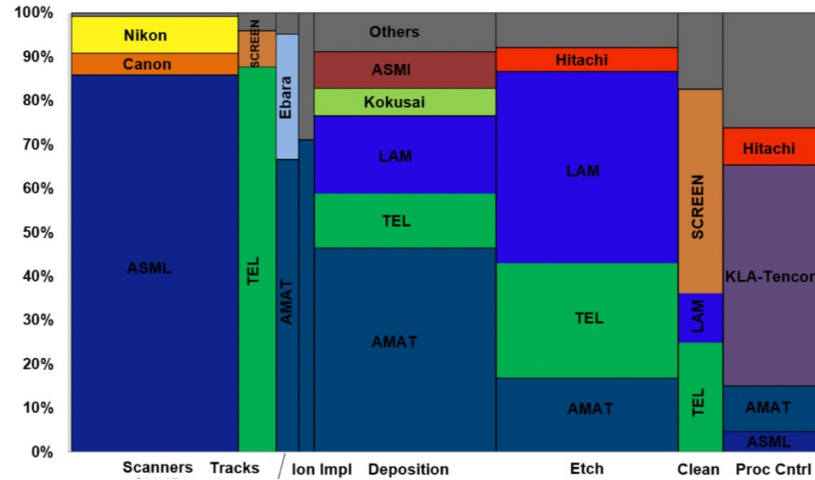
Source: IC Insights

Chip design costs



Source: M. Lapadeus, Semi Eng.

Equipment Market Share



Source: VLSI Research, 2020

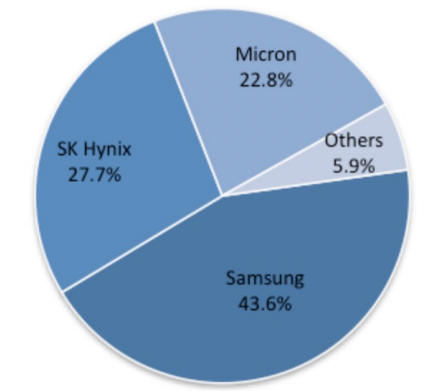
Logic/Foundry platforms

SilTerra										
X-FAB										
Dongbu HiTek										
ADI	ADI									
Atmel	Atmel									
Rohm	Rohm									
Sony	Sony									
Mitsubishi	Mitsubishi									
ON	ON									
Hitachi	Hitachi									
Cypress	Cypress									
Sony	Sony									
Infineon	Infineon									
Sharp	Sharp									
Freescall	Freescall									
Renesas (NEC)	Renesas									
Toshiba	Toshiba									
Fujitsu	Fujitsu									
TI	TI									
Panasonic	Panasonic									
STMicroelectronics	STM									
HLMC	HLMC									
UMC	UMC									
IBM	IBM									
SMIC	SMIC									
AMD	AMD									
Samsung	Samsung									
TSMC	TSMC									
Intel	Intel									
180 nm	130 nm	90 nm	65 nm	45 nm/40 nm	32 nm/28 nm	22 nm/20 nm	16 nm/14 nm	10 nm	7 nm	5 nm

FINFET

Source: Wikipedia

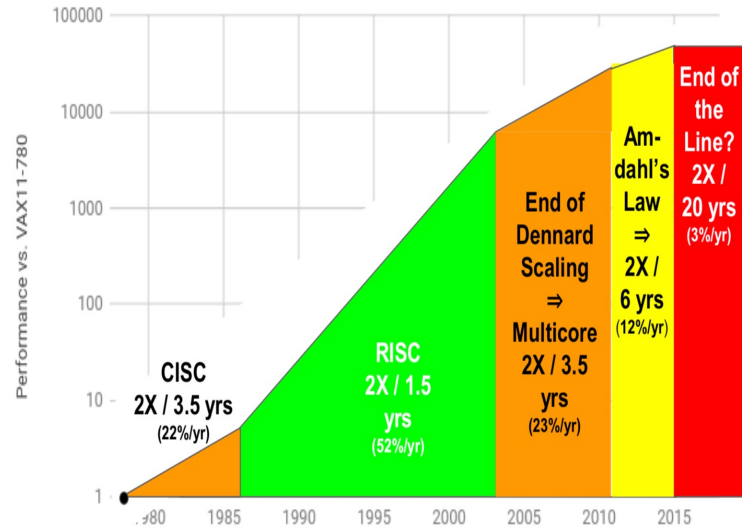
DRAM Market Share



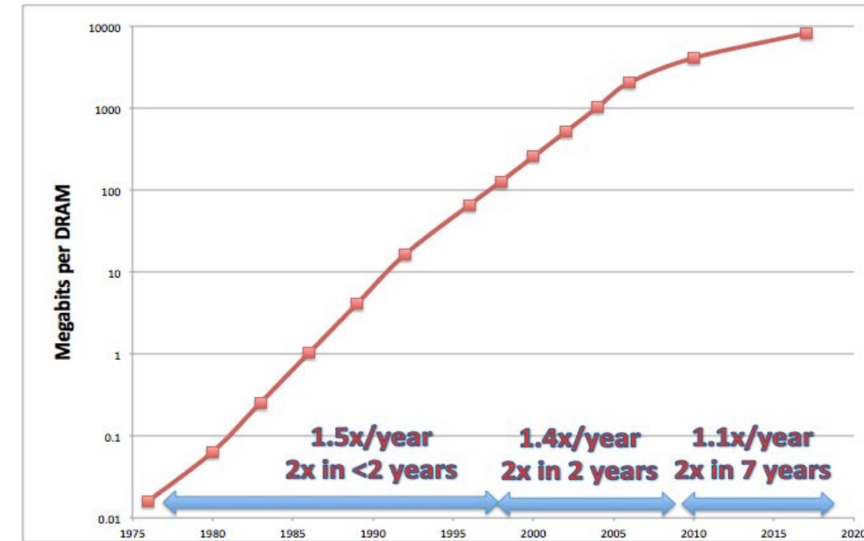
Source: IC Insights

Evidence of Moore's Law slowdown – scaling is in trouble

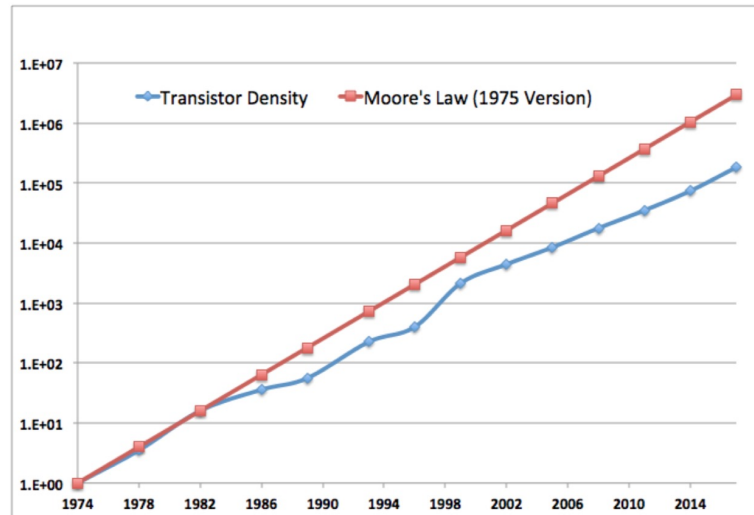
CPU single core performance



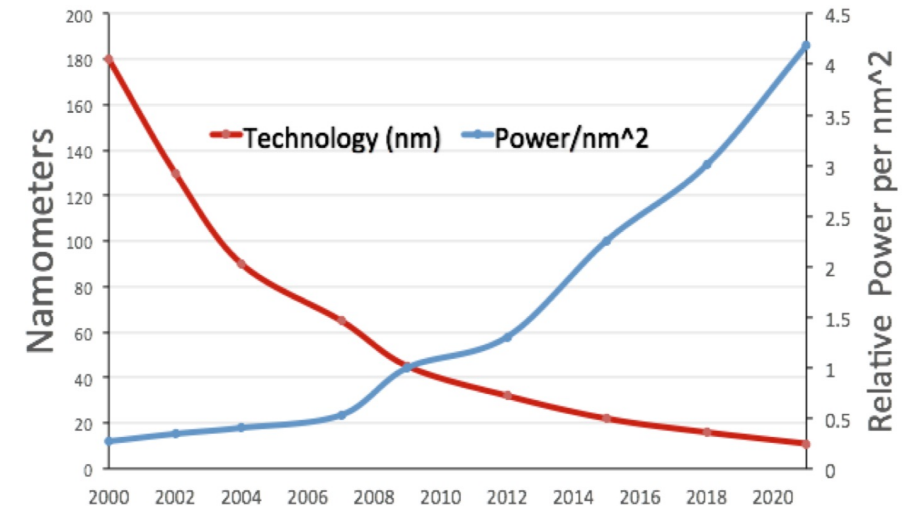
DRAM density roll off



Intel CPU density roll off

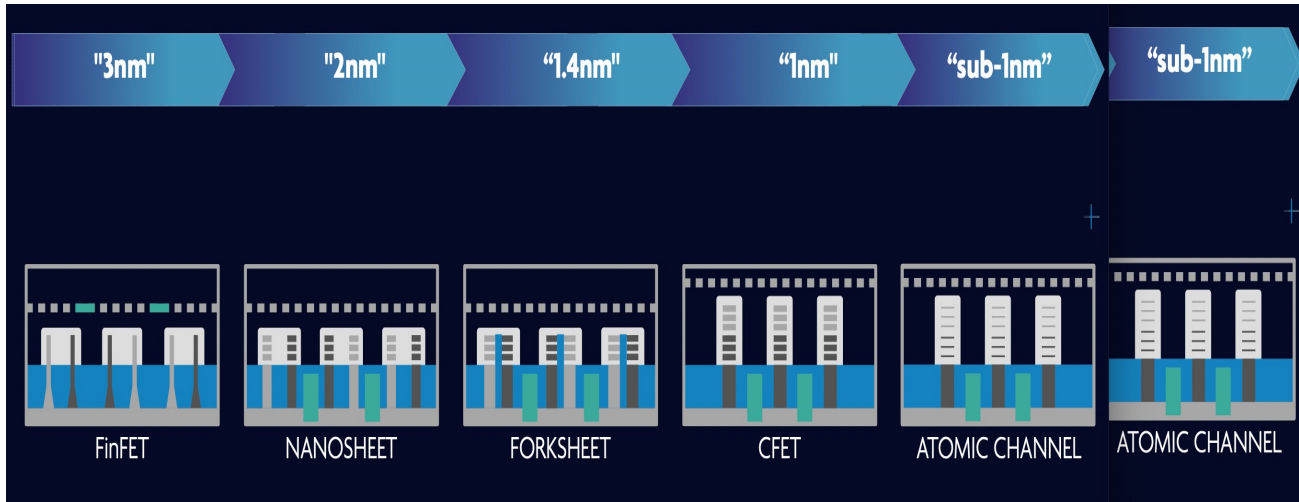


Transistor power takes off

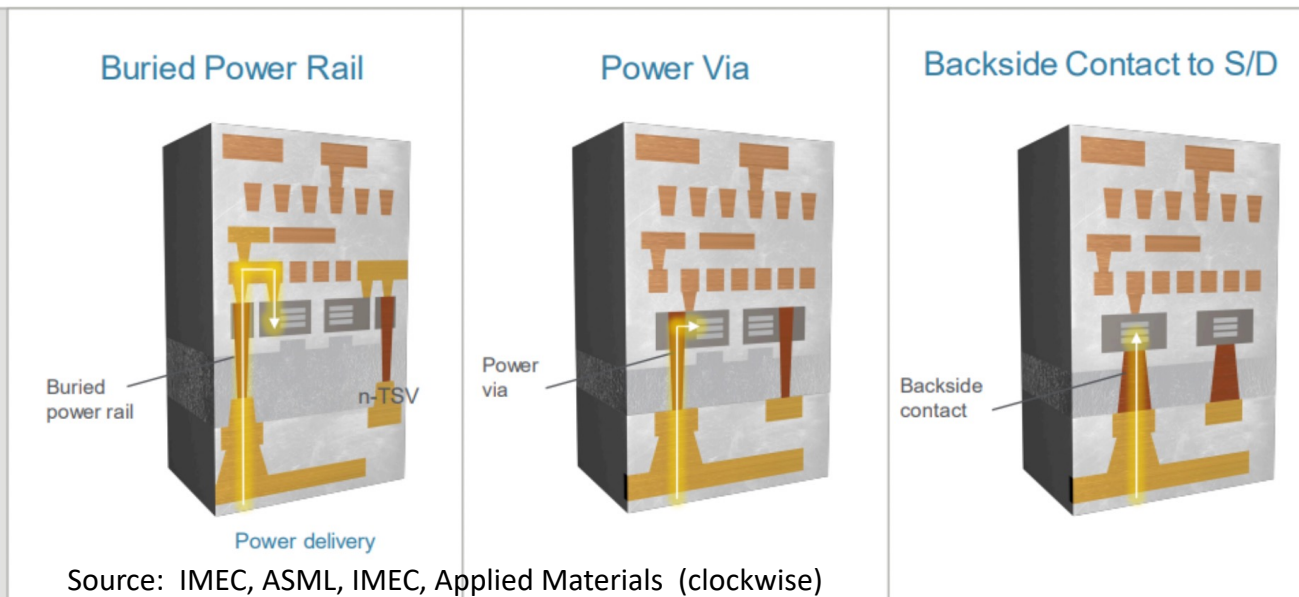


Some consolation until the next new thing: solid roadmap for next decade

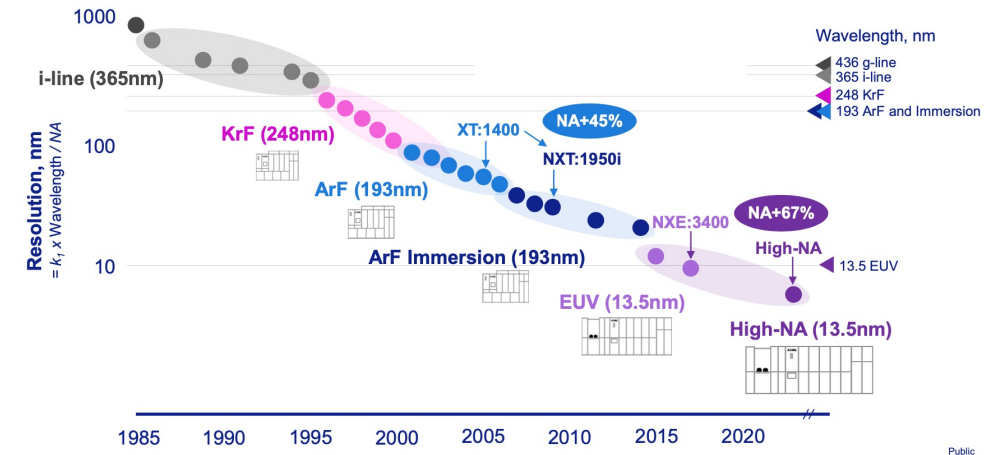
CMOS Roadmap to <1.0 nm



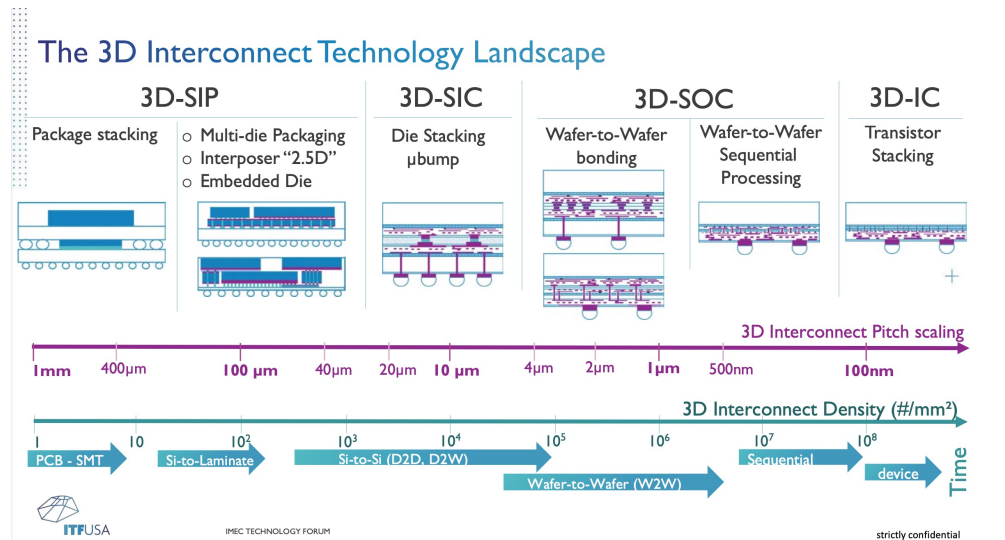
Backside Power Distribution



EUV Lithography



Advanced packaging

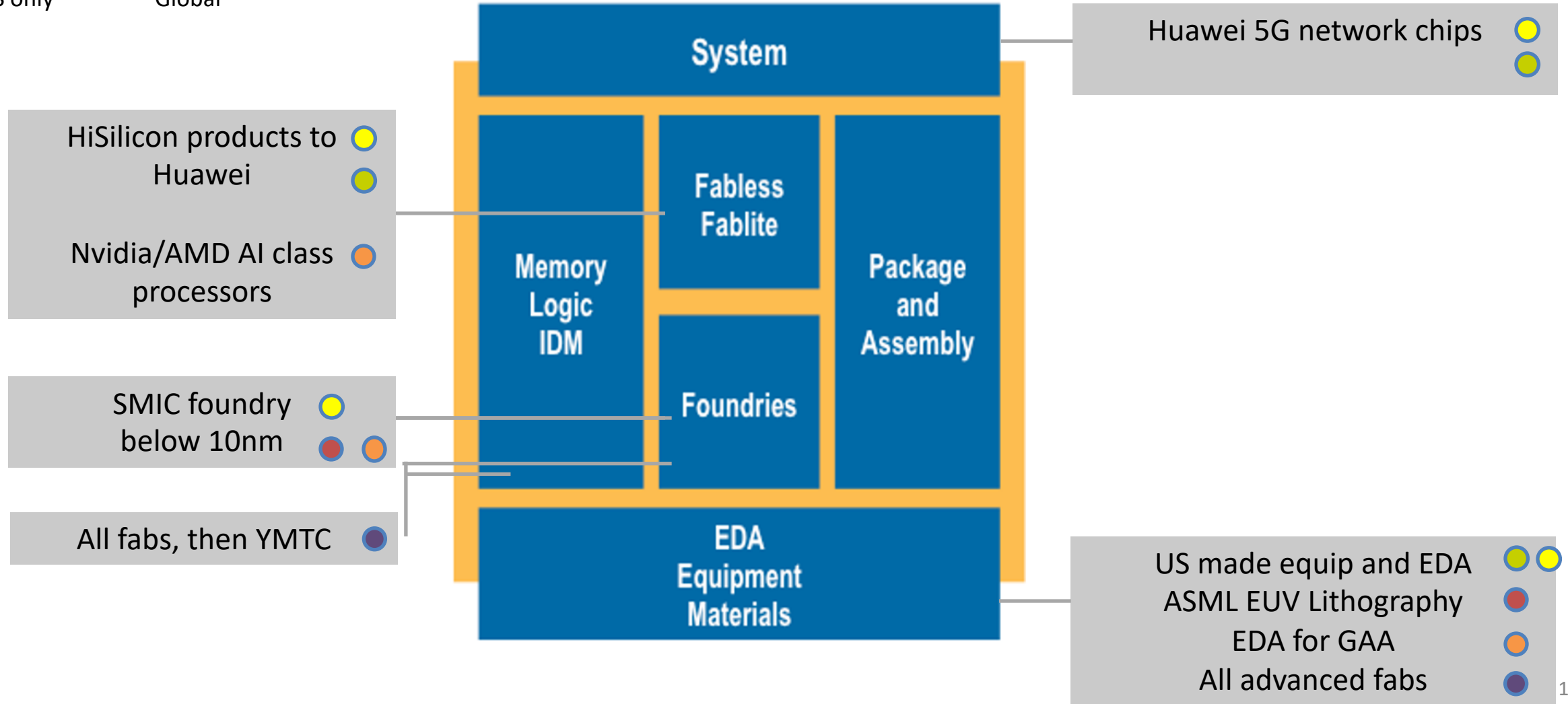
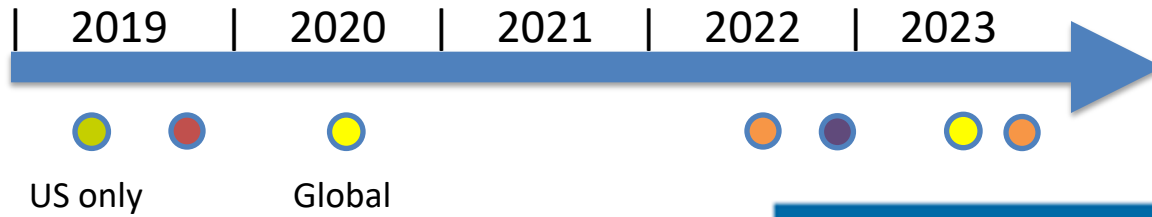


System companies becoming silicon houses



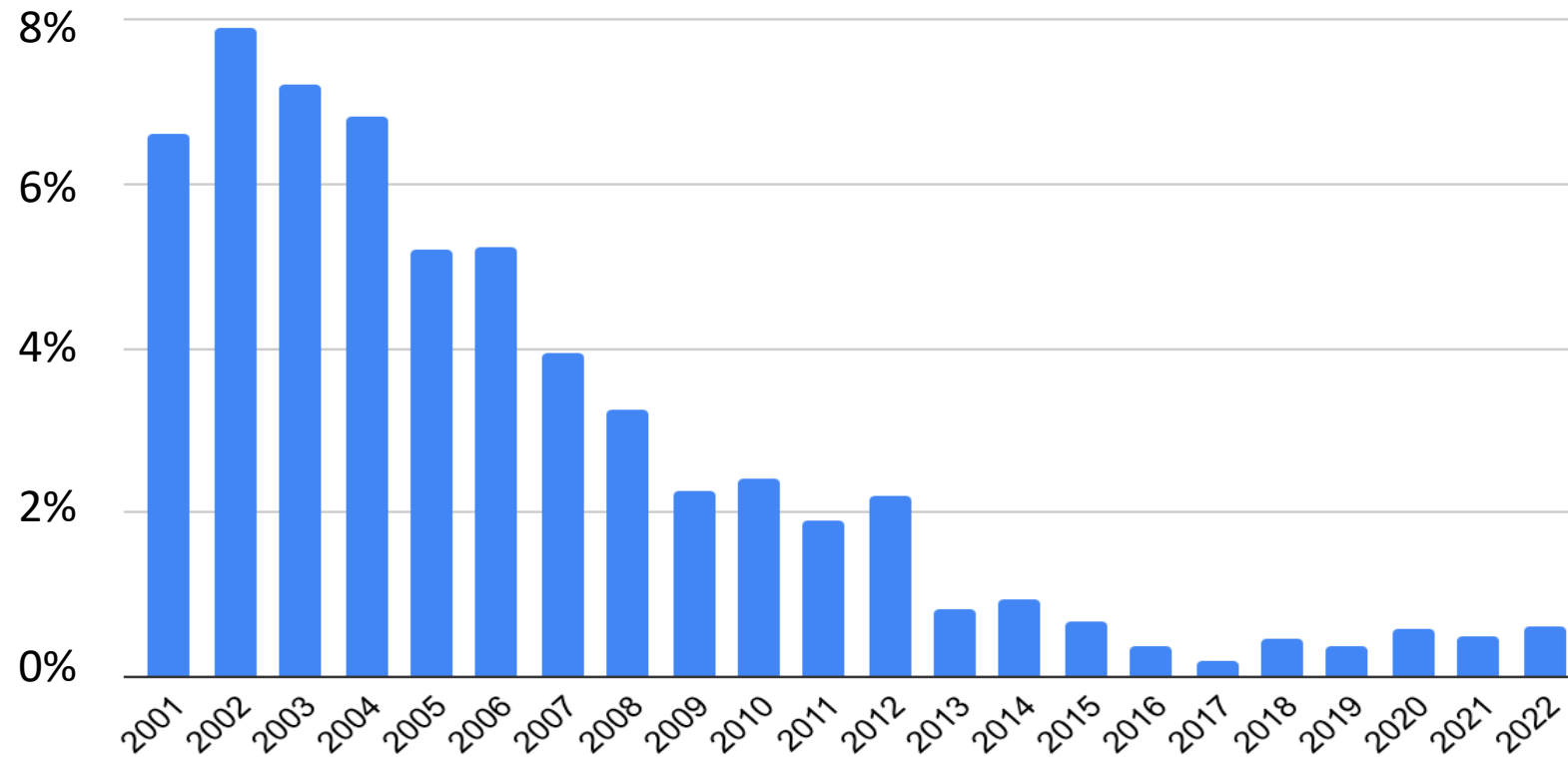
	Apple	Google	Amazon	Microsoft	Meta	Baidu	Cisco	Huawei	Samsung	IBM
System	↓	↓	↓	↓	↓	↓	↓	↓	↑	↑
Chip Design limited	↓	↓	↓	↓	↓	↓	↓	↓	↑	↑
Chip Design extensive	↓			↓		↓	↓		↑	↑
Chip Mfg									↑	↑

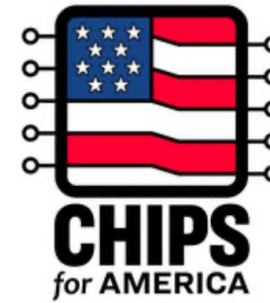
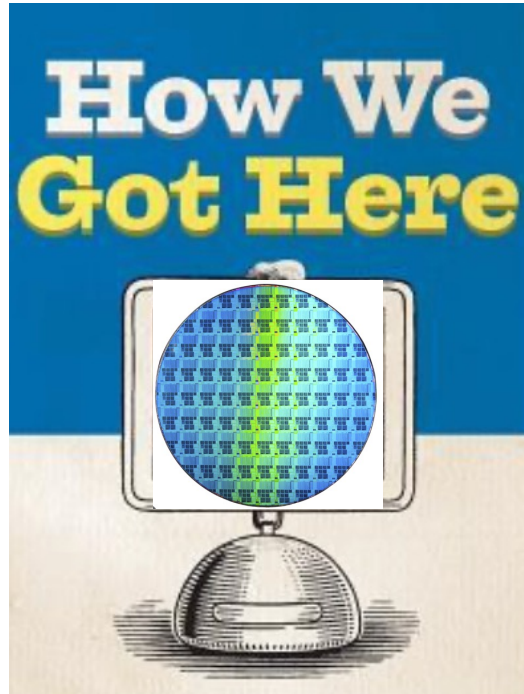
China export controls and trade restrictions are stressing globalism



Venture Capital has moved past semiconductors to software and services

VC investment in semiconductor startups as % of total VC funding

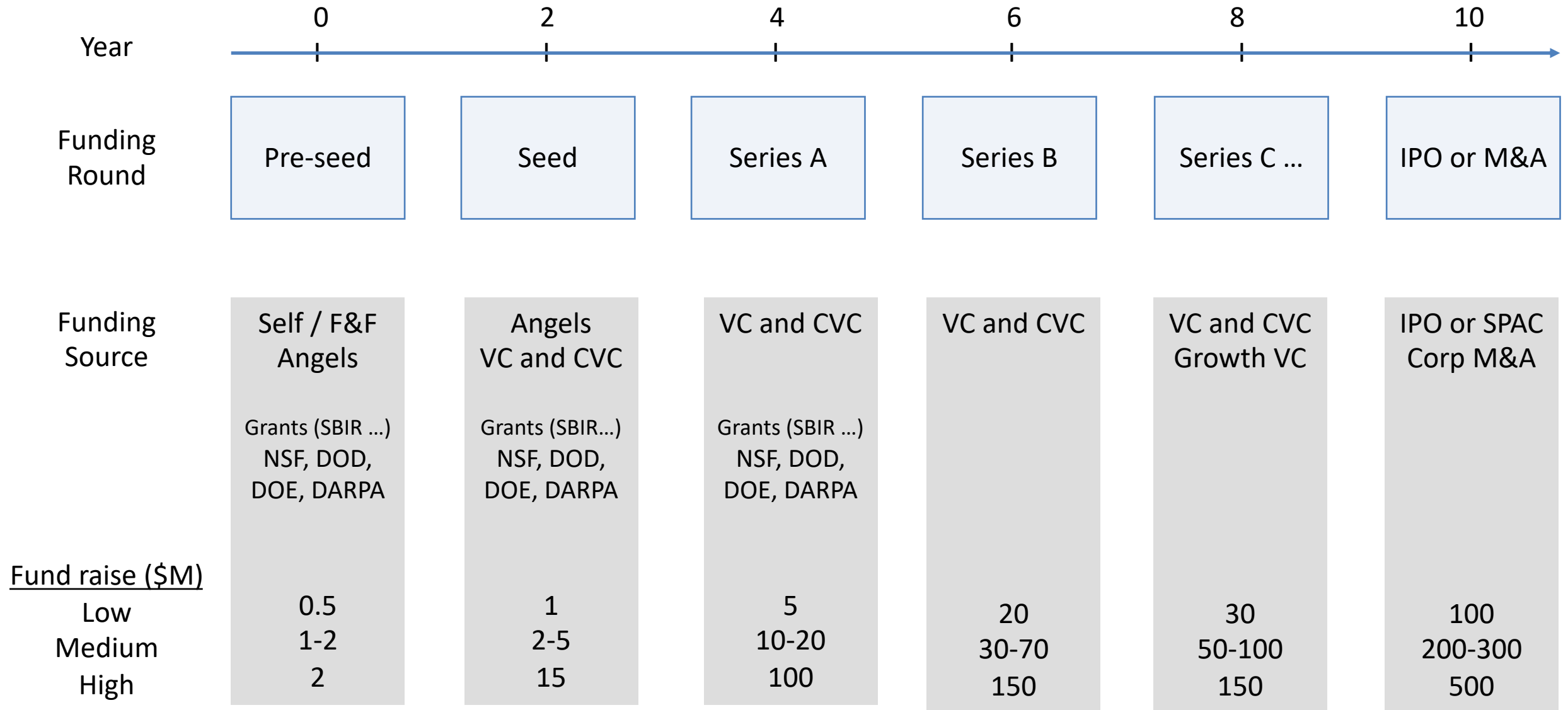




Recommendations
Policy and
Partnerships

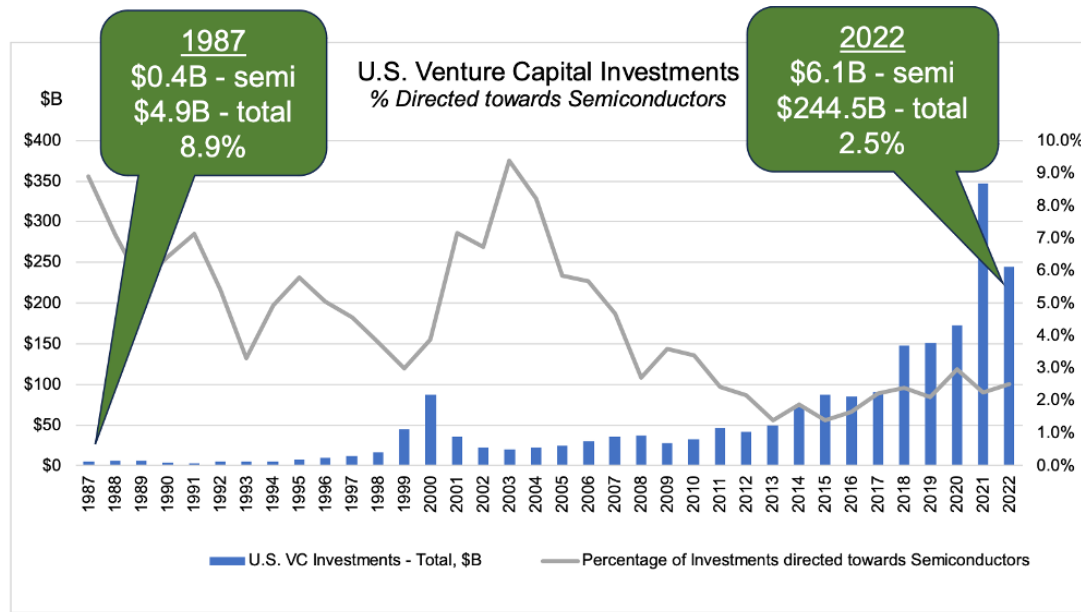


Typical semiconductor startup timeline



Dramatic ramp of venture investment in the last decade – semis not benefiting

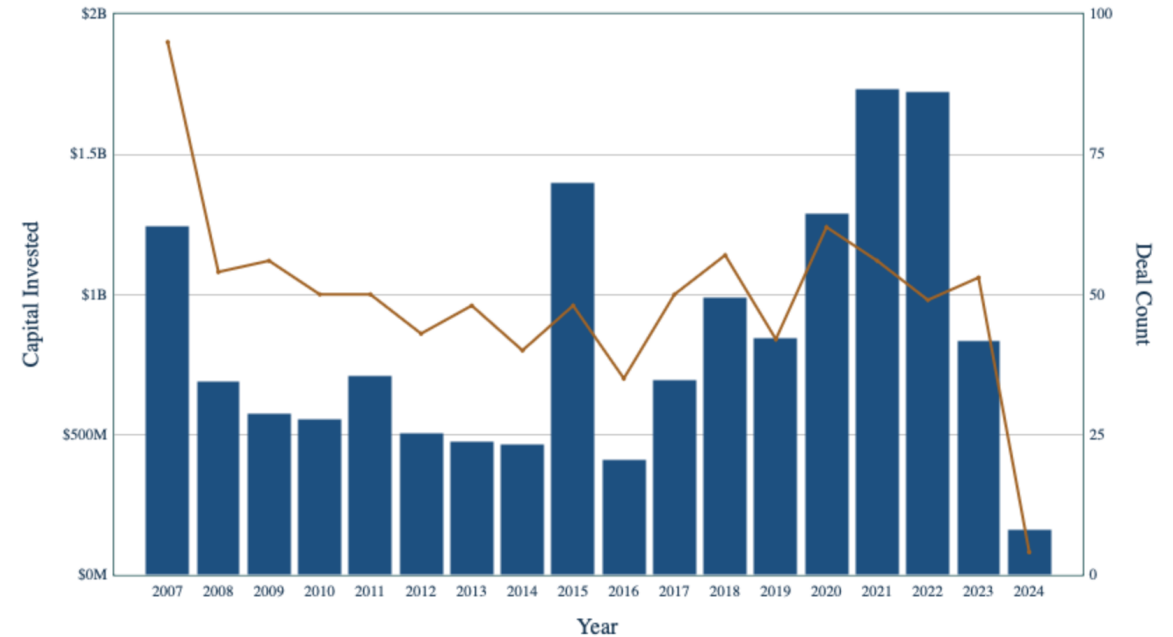
US VC investments (25 years)



Sources: 1987-1996 Data (Total, Semi): NSF, Venture Economics Investor Services, October 1998; 1997-2003 Data (Total, Semi): NSF, Dow Jones VentureSource, 2014; 2004-2022 Data (Total): National Venture Capital Associations (NVCA); Pitchbook, 2023; 2004-2022 Data (Semi): Pitchbook, Deloitte, December 2021

CHIPS IAC Organization/PPP Working Group November 8, 2023 Public Meeting

US VC investments in semiconductors (15 years)



Pitchbook

Venture Capital and Corporate VC: who are the major players in semiconductors?

VC by Deal Count

Celesta	26
Walden International	24
A&E Investments	23
Eclipse Ventures	15
Foothill Ventures	15
Sutter Hill Ventures	15
Alumni Ventures	13
GSR Ventures	12
InQTel	12
Cambium	10
DCVC	10
Foundation Capital	10
Kleiner Perkins	10
Lux Capital	10
Bessemer Ventures	9

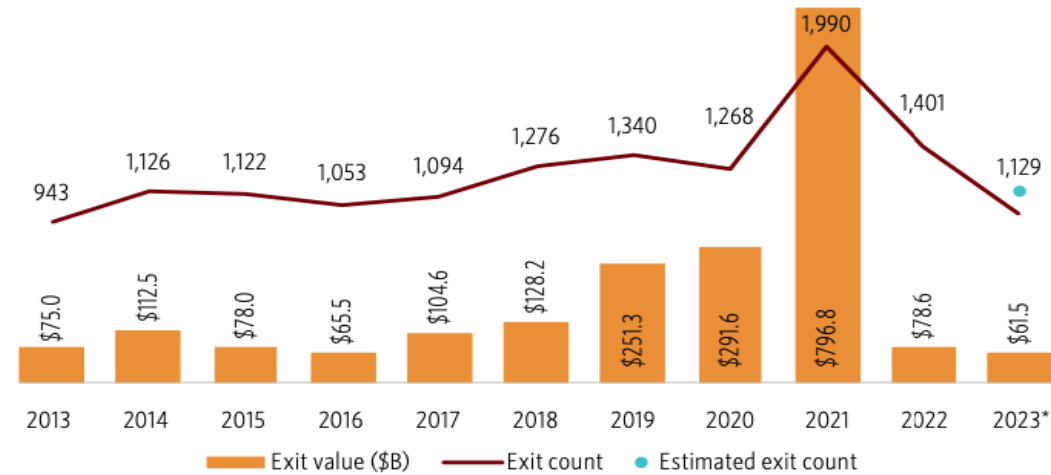
CVC by Deal Count

Intel Capital	74
Applied Ventures	16
Samsung Catalyst Fund	16
TEL Venture Capital	11
Cisco Investments	10
Lockheed Martin Ventures	10
AMD Ventures	9
Dell Tech Capital	9
Western Digital Capital	7
M12	6
Xilinx Ventures	6
TDK Ventures	5
3M Ventures	4
Airbus Ventures	4
Eni Next	4

Venture Capital exits and funds raised – rapid reversal of positive trends

VC exits (IPO, M&A)

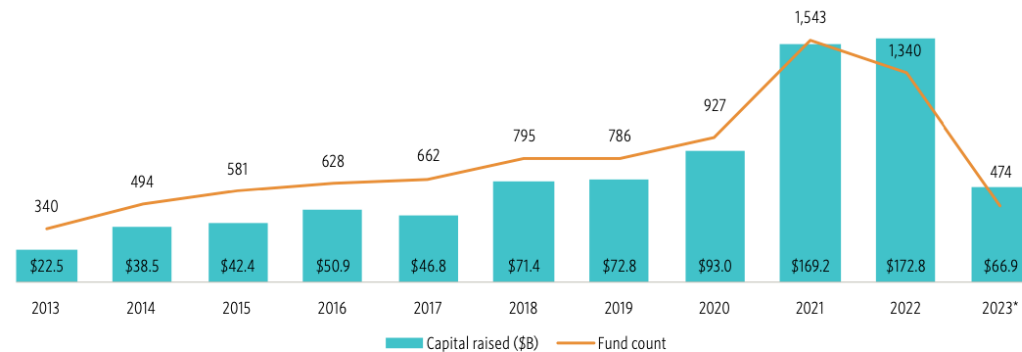
US VC exit activity



PitchBook-NVCA Venture Monitor • *As of December 31, 2023

VC capital raised

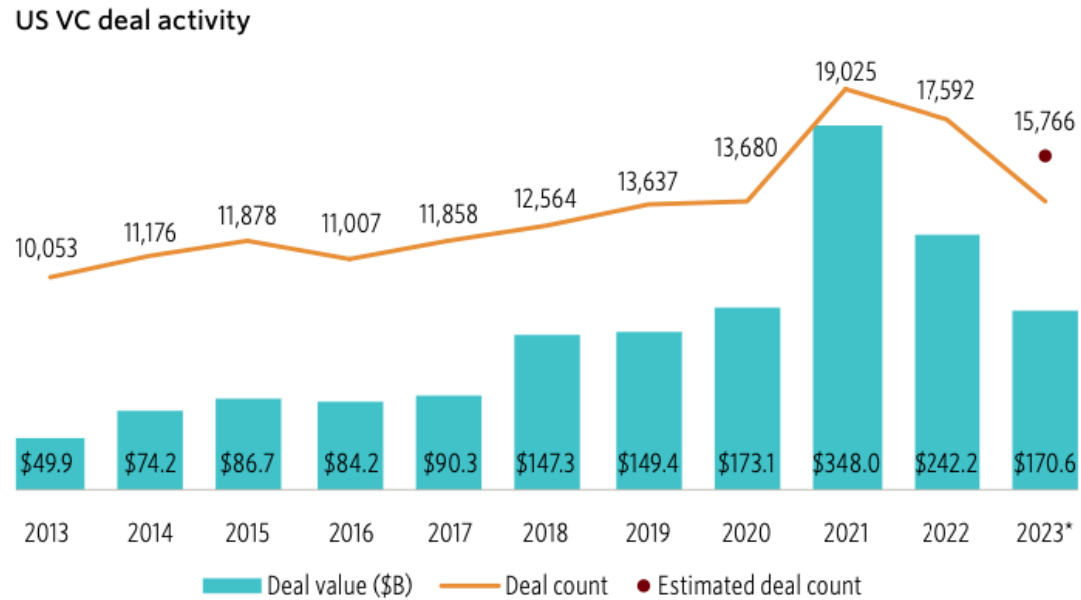
US VC fundraising activity



PitchBook-NVCA Venture Monitor • *As of December 31, 2023

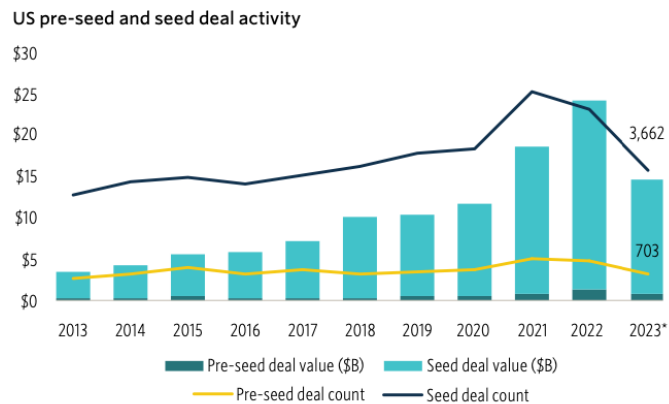
Downturn in Venture Capital startup funding from 2021 peak

US VC investments – All stages



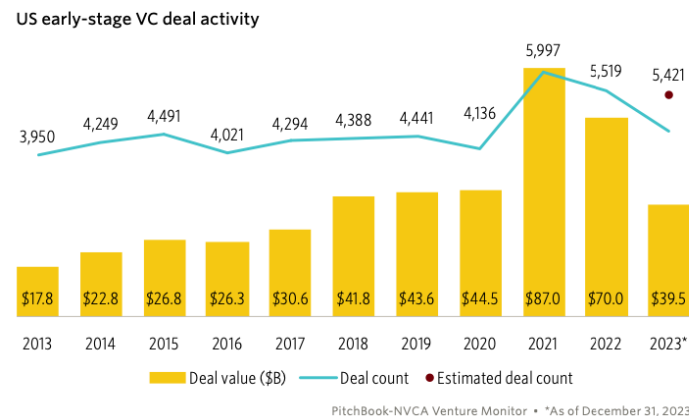
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Pre-seed and Seed



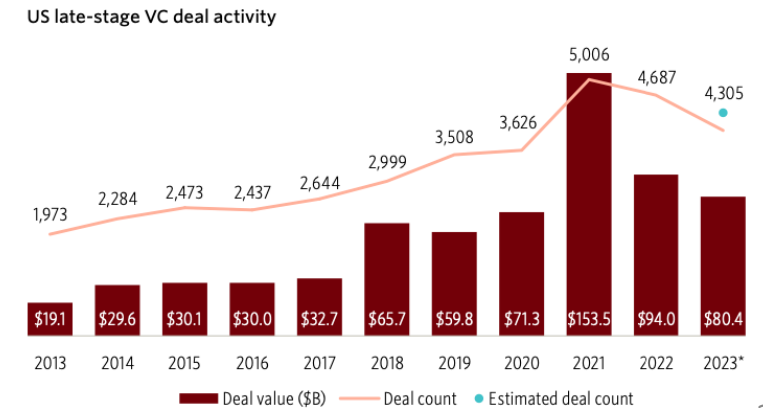
PitchBook-NVCA Venture Monitor • *As of December 31, 2023

Early Stage (Series A/B)



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Late Stage (Series C/D)

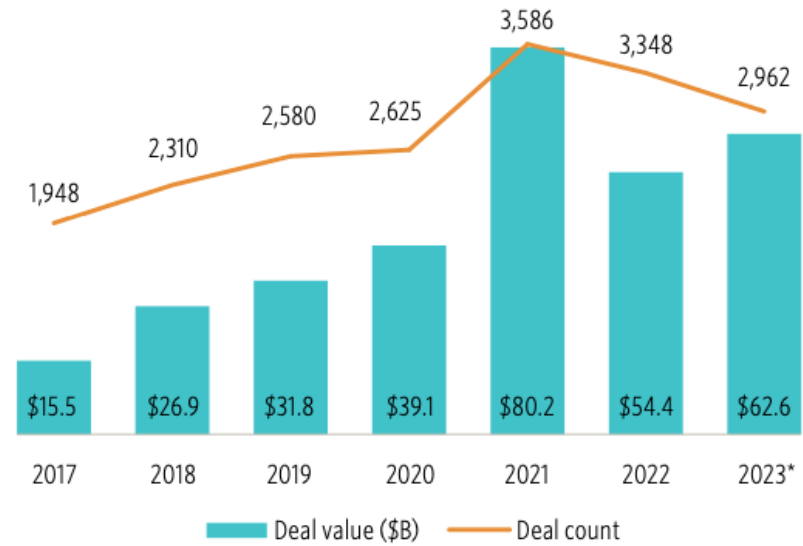


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Venture Capital investments in AI/ML have escalated

VC funding

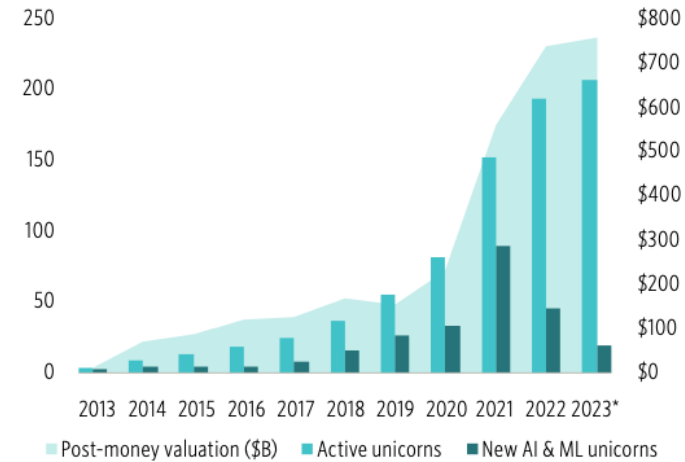
US AI & ML VC deal activity



PitchBook-NVCA Venture Monitor • *As of December 31, 2023

AI startup unicorn formation

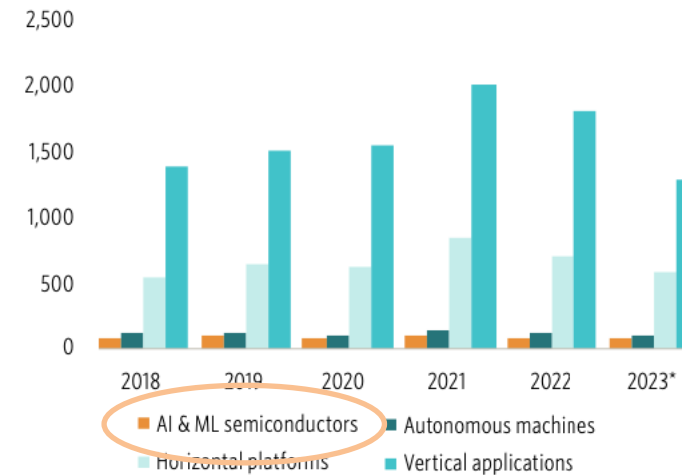
US AI & ML unicorn count and aggregate post-money valuation (\$B)



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AI funding by sector

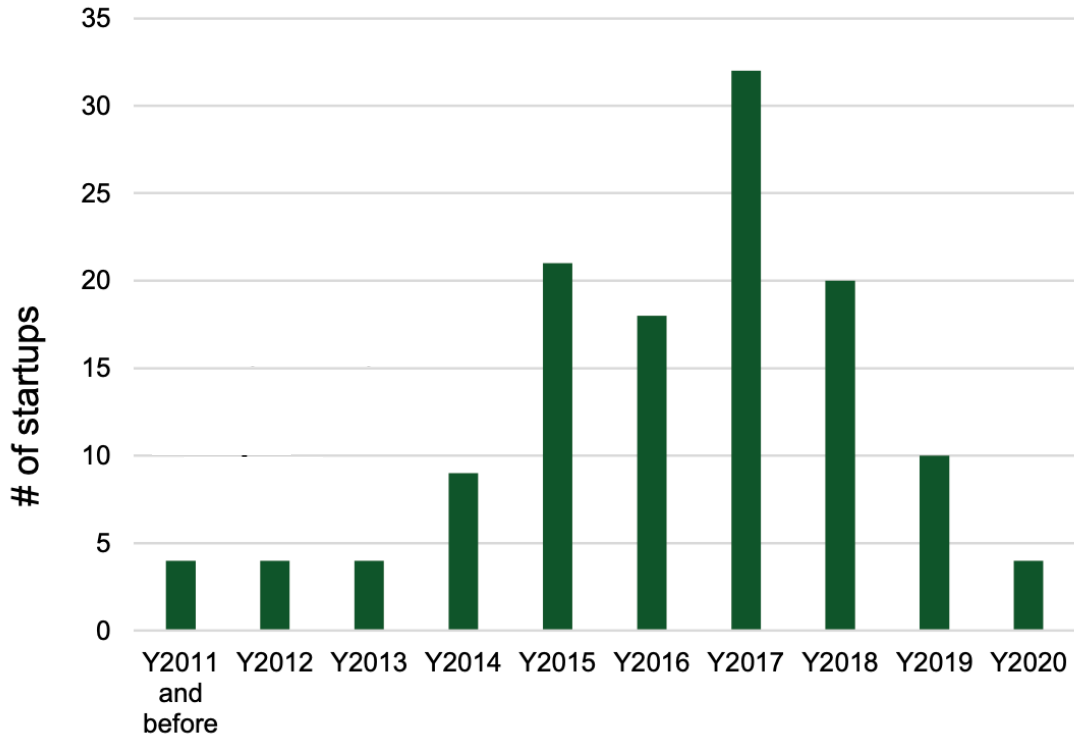
US AI & ML VC deal count by segment



PitchBook-NVCA Venture Monitor • *As of December 31, 2023

The first wave of domain specific accelerators / architectures for AI

AI/ML startups formation



Source: Woodside Capital Partners

Von Neumann

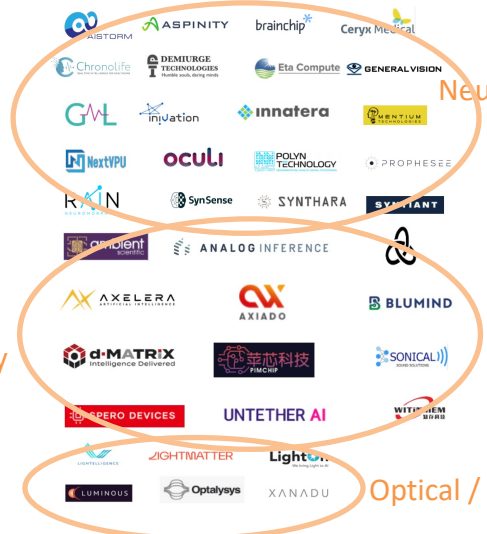
Non-Von Neumann

In-Memory

Optical / Photonics

Edge

Cloud



Neuromorphic



VC model at a glance

Goal is return 3-5x or 20-30% annual IRR over the 10-year life of the fund

Invest fund in 20-25 companies which represent 0.1-1% of deal flow

Hits driven business – need 1-3 companies to return 10-100x of investment

VCs are compensated 2% of fund annually for OpEx and retain 20% (carry) of profits

Each startup funding round is lead by a new VC that sets the valuation and investing terms for others, and for existing investors, exercising pro-rata rights is key

VCs raise follow-up funds based upon track record of the prior funds

Investments in semiconductors are less attractive compared to software and services

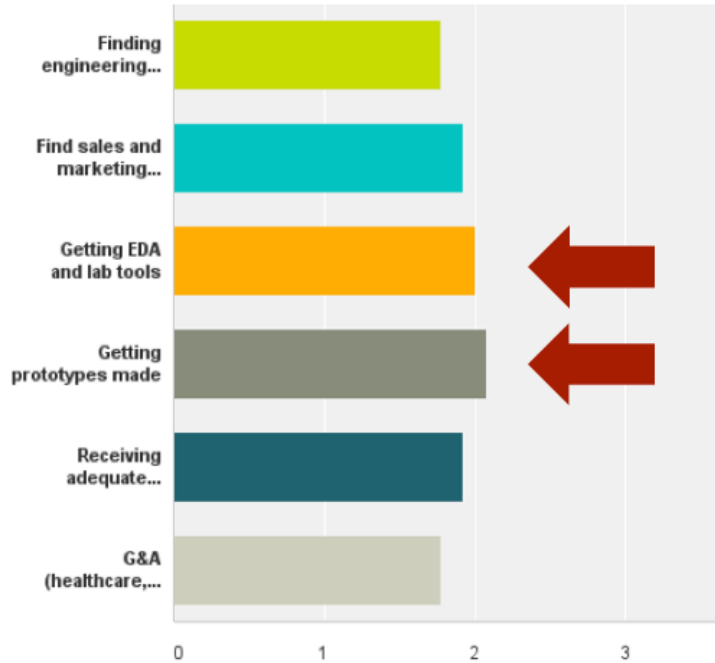
- Higher capital required
- Longer time to revenue ramp
- Higher innovation failure rates
- Longer time to liquidity
- Lower returns

Semiconductors requires extensive and specific due diligence, a skill mostly atrophied

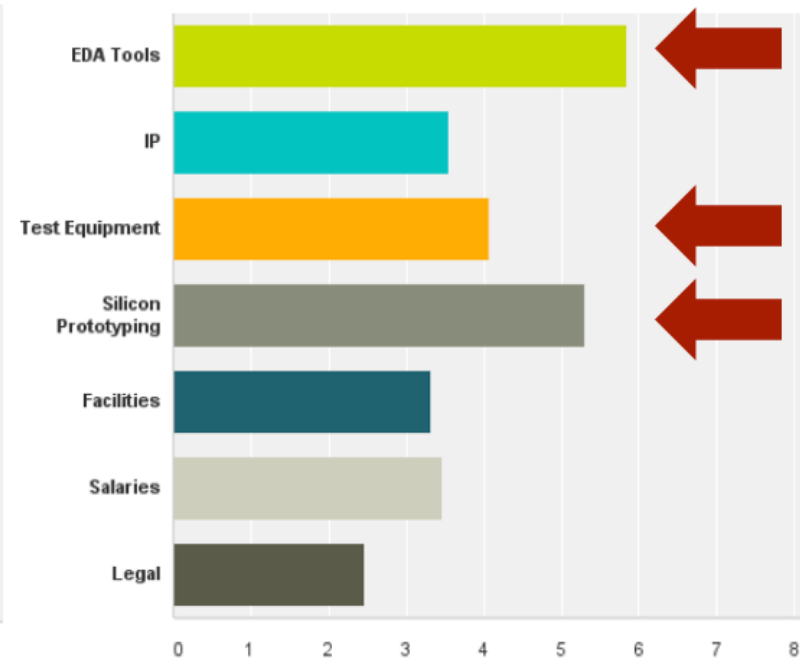
Product-market fit is hard to predict based upon early measures of traction and adoption

Challenges facing semiconductor startups

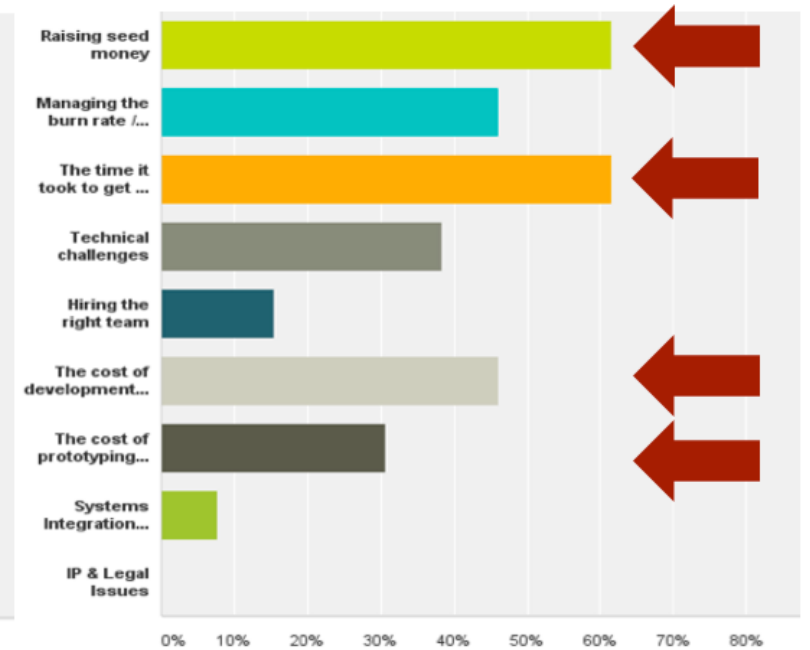
Rank Issues



Rank Expenses



Top Challenges



Time, EDA, Prototypes, Test, \$'s ←

Source: 70 startups surveyed in 2014 & > 500 startups 2015 - 2023

Incubator and accelerator services have helped startups in other arenas

Office space

Infrastructure: HR, Fin, Legal, IP, IT

Curriculum

Events (Demo/Pitch Day)

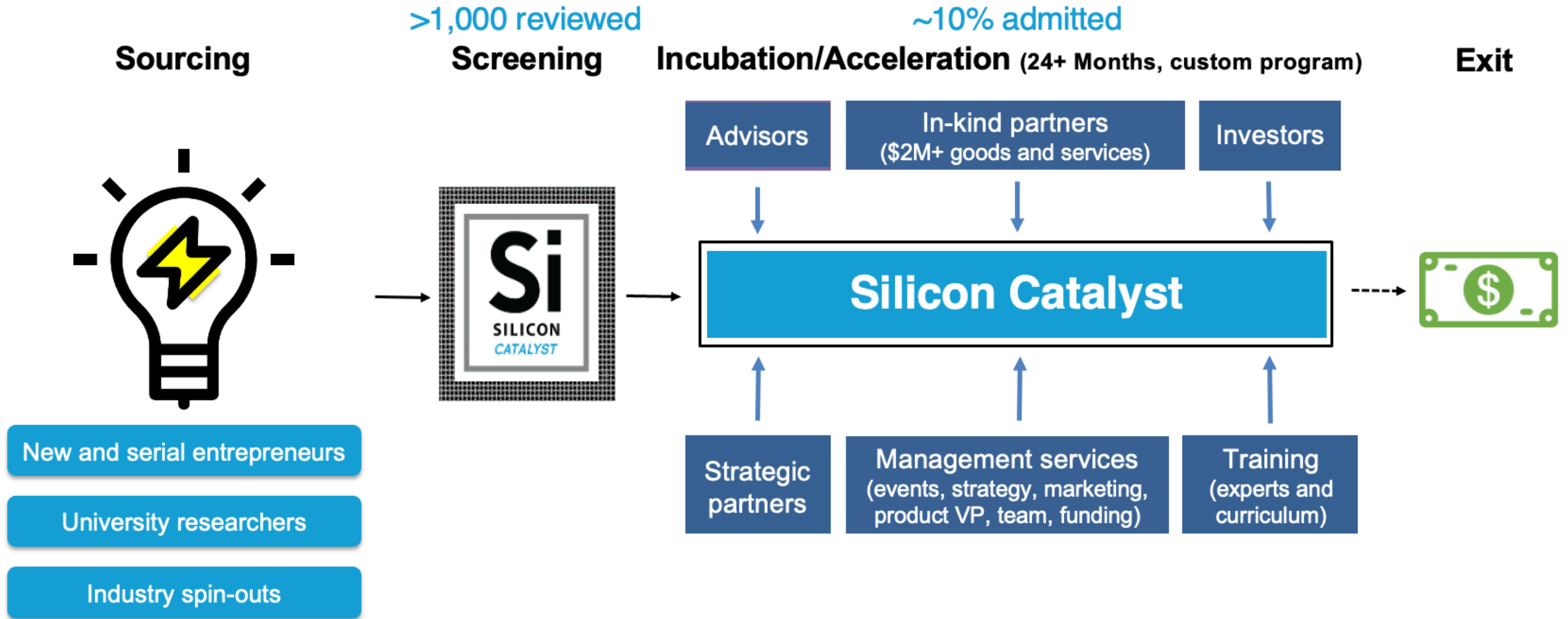
Ecosystem access

Prototyping/software/services

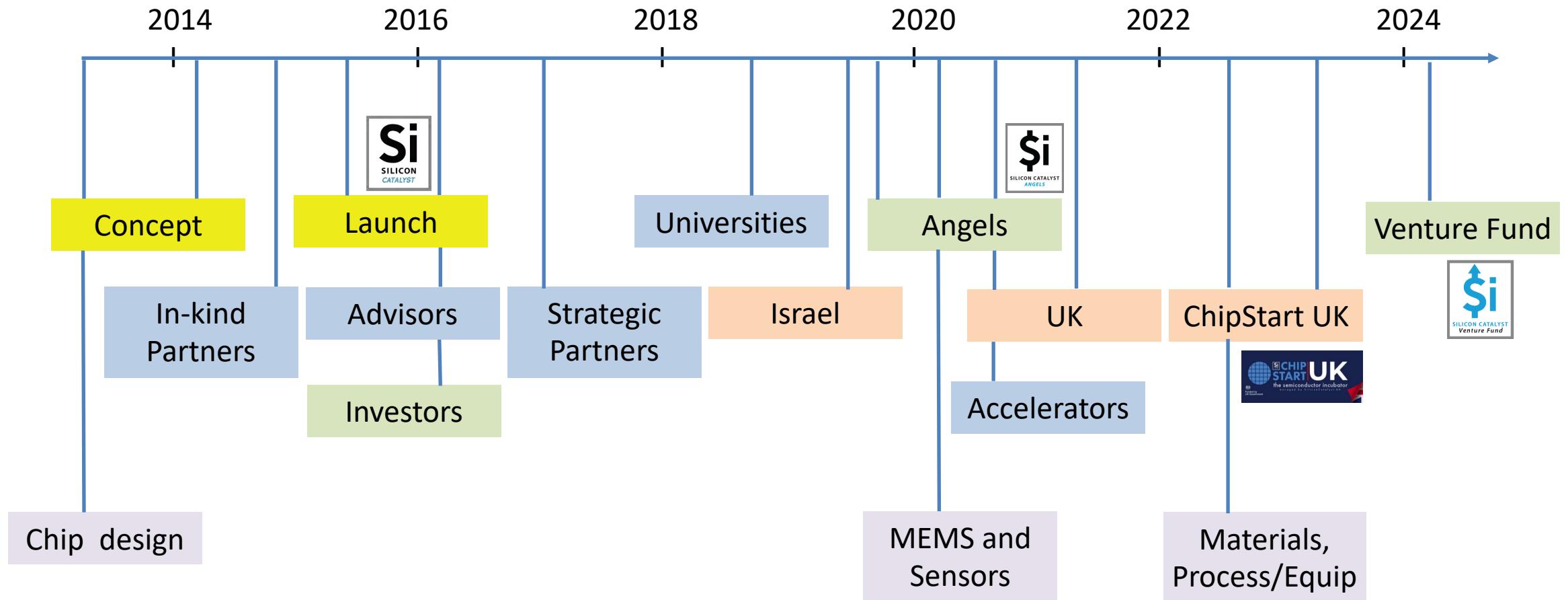
Mentors / Advisors

Seed funding

Silicon Catalyst accelerator model is tuned to semiconductor startup needs



Silicon Catalyst timeline



Silicon Catalyst ecosystem has grown over its first 9 years

Over 90 startups – portfolio >\$1.9B valuation, >\$500M raised



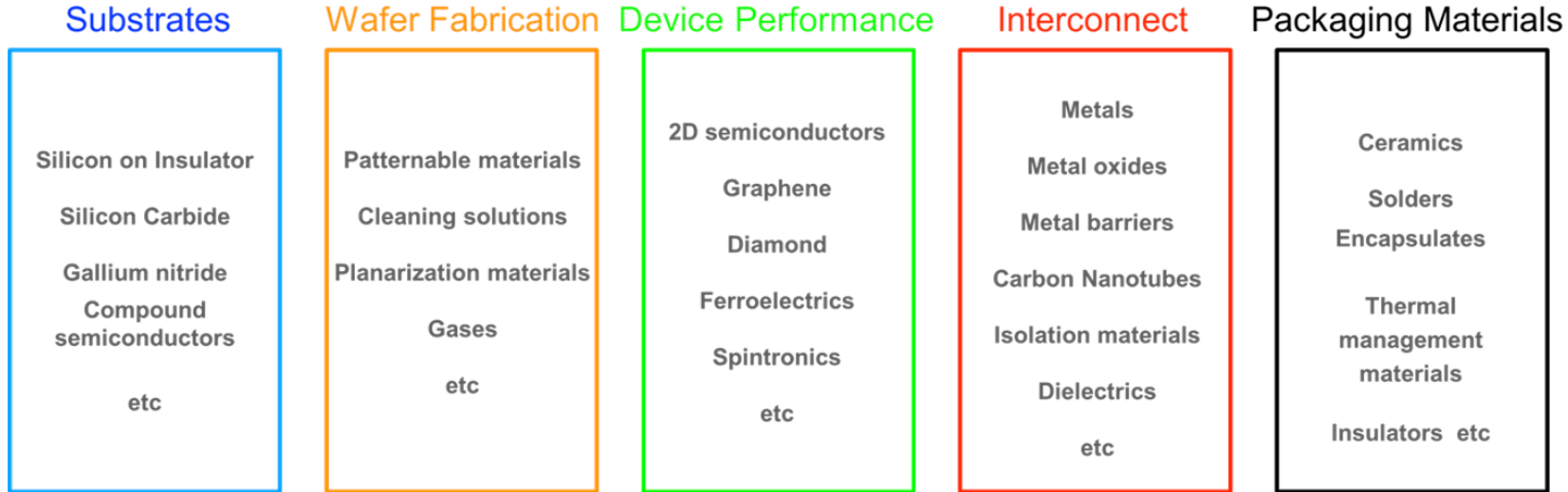
Silicon Catalyst services are available from the industry's ecosystem

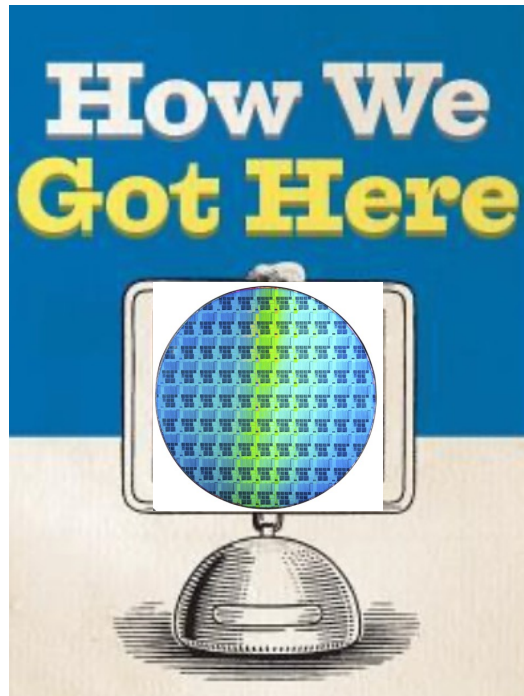
EDA	IP	Services	Foundry	Back-end	Business
<p>¹ Low Volume; ² High Volume Yield Improvement; ³ Israel Only; ⁴ UK Only</p>					



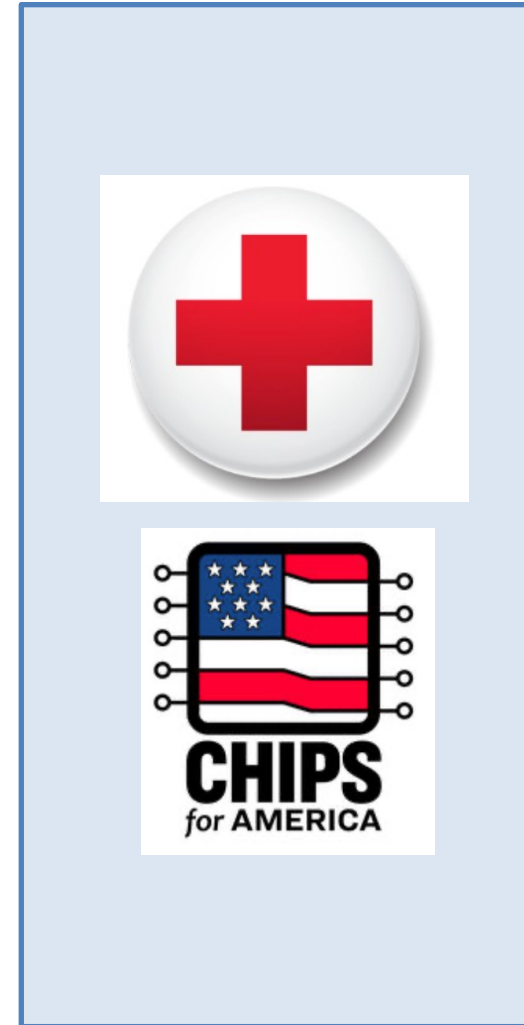
Within semiconductors, what's not receiving its share of love?

Materials/process changes
New materials and devices
New equipment and processes
EDA for emerging technologies





BEHIND THE
STARTUP



Recommendations
Policy and
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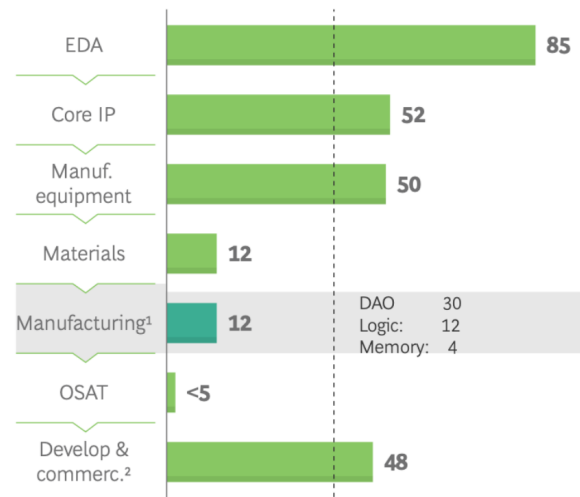


CHIPS and Science Act of 2022 – signed into law in August

CHIPS Act: \$52B funding and \$24B tax incentives over 5 years

\$39B for manufacturing outcomes

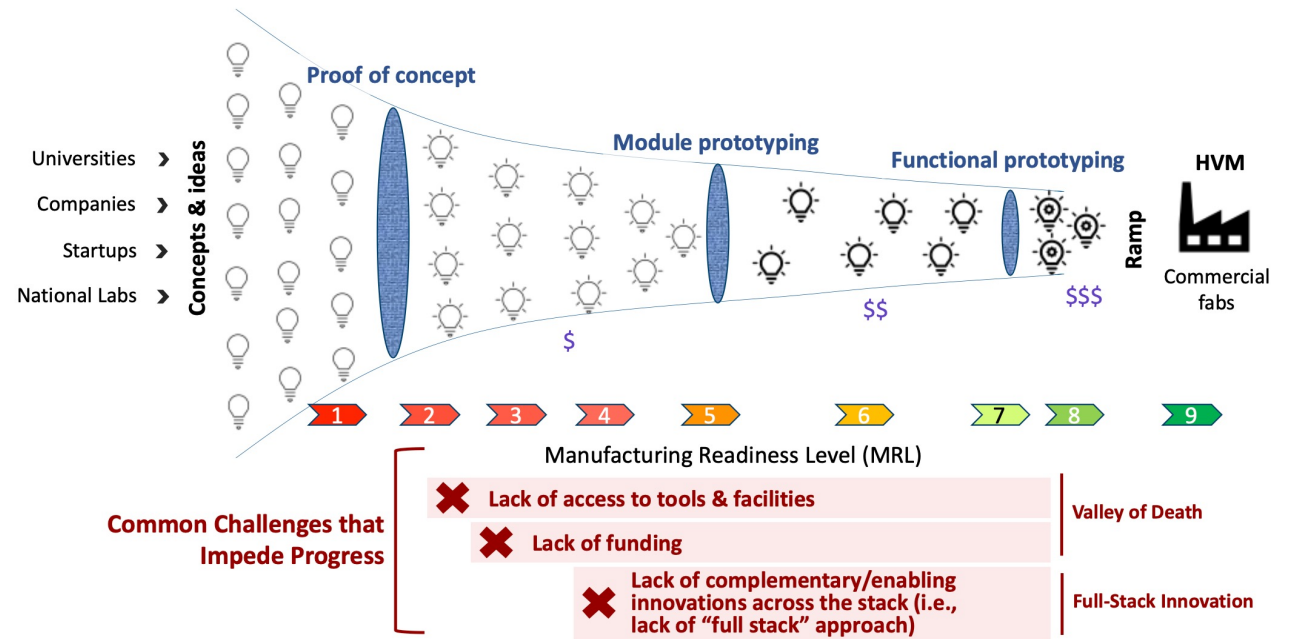
US share across the semiconductor value chain, 2018 (%)



A. Varas, R. Varadarajan, J. Goodrich, and F. Yinug, September 2020, BCG & SIA

\$24B (25%) in facility and equipment tax credits

\$11B for R&D (NSTC) and Advanced Packaging (NAPMP)





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MITRE ENGENUITY

\$2B for DOD “Commons” - regional hubs for prototyping

The innovation gap is what the CHIPS Act R&D provisions are about

 
\$1.5B – 5 yrs

 nCORE

\$200M – 5 yrs

U.S. DEPARTMENT OF
 BES

 MRSEC
STSC



GAPS
Prototyping at scale
Scale-up business model
Startup funding
Gov. agency coordination



20 years

15

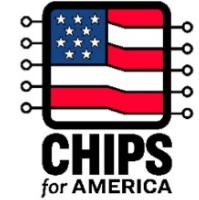
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5

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TRL1

TRL9



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Industry



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Chair
MRS Business
and Technology
Advisors



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**Meredith
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**Debo
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**Alex
Oscilowski**
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Anthony Yer
ASML
Technology
Center



**Scott
DeBoer**
Micron



**Todd
Younkin**
SRC

Ecosystem/ Customers



**Daniel
Armbrust**
Silicon
Catalyst



Bill Chappell
Microsoft



Charles Gray
Ford Motor
Company

Academia/Other Stakeholders



James Ang
Pacific
Northwest
National
Laboratory



Michael Fritze
Potomac
Institute for
Policy Studies



**Carol
Handwerker**
Purdue
University



**Rajarao
Jammy**
MITRE
Engenuity



**Tsu-Jae King
Liu**
University of
California
Berkeley



Willy Shih
Harvard
Business
School



**Brandon
Tucker**
Washtenaw
Community
College



**H.S. Philip
Wong**
Stanford
University

WG member only

WG member only

WG member only

IAC timeline and charges

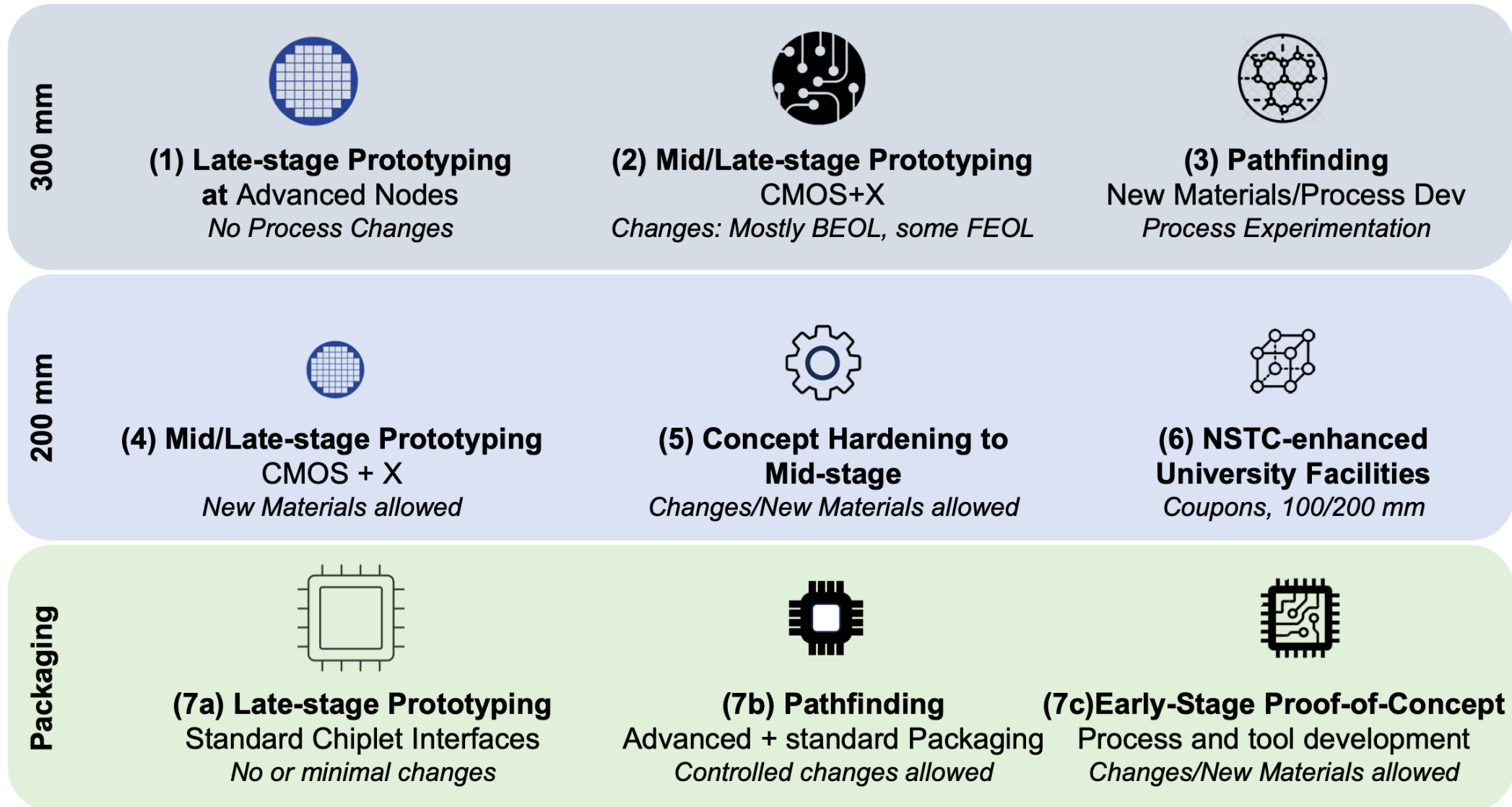
		R&D GAPS WG	PPP WG	WORKFORCE WG	COMBINED WG
Sep '22	Announcement				
Dec '22	#1 - Wash DC	R&D Gaps	Organization and PPP	Workforce	x
Feb '23	#2 - Virtual	R&D Gaps	Organization and PPP	Workforce	x
Jun '23	#3 - Wash DC	Advanced Packaging	IP and NSTC	Workforce	Sequencing of Priorities
Nov '23	#4 - Virtual	Metrology and Standards	Investment Fund	x	x

Recommendation 1:

Establish a set of five key capabilities aimed to lower the barriers to entry and success for innovators. These capabilities will rely on a network of physical and virtual facilities with a digital backbone to reduce design and experimentation cycle time. These capabilities should benefit the *entire community of stakeholders* and it should be of primary importance to increase access to and reduce the effective cost of accessing these capabilities over time.

- 1) **Establish easily accessible prototyping capabilities** in multiple facilities and enact the ability to rapidly try out CMOS+X at a scale that is relevant to industry
- 2) Create a semiverse digital twin
- 3) **Establish chiplets ecosystem and 3D heterogeneous integration platform for chiplet innovation and advanced packaging**
- 4) Build an accessible platform for chip design and enable new EDA tools that treat 3D (monolithic or stacked) as an intrinsic assumption
- 5) **Create a nurturing ecosystem for promising startups**

IAC prototyping analysis



American Semiconductor Research: Leadership Through Innovation

S I A SEMICONDUCTOR
INDUSTRY
ASSOCIATION

WINNING THE FUTURE.

A Blueprint for Sustained U.S. Leadership in Semiconductor Technology

April 2019

S I A SEMICONDUCTOR
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ASSOCIATION

Prototyping and Piloting Infrastructure

The NSTC and NAPMP must go beyond only funding or coordinating existing research efforts. The two should play an active role in facilitating access to prototyping facilities or to advanced simulation and modeling software. They must also expand access to capabilities that facilitate technology transition from lab-to-fab – such as prototyping and piloting – and ensure the accessibility of these capabilities to researchers and startups. By facilitating access to these capabilities, the NSTC and NAPMP will broaden the pool of potential innovations able to traverse phases from basic research to scaling and reach commercial usefulness.



REPORT TO THE PRESIDENT
Revitalizing the U.S.
Semiconductor Ecosystem

Executive Office of the President
President's Council of Advisors on
Science and Technology

September 2022

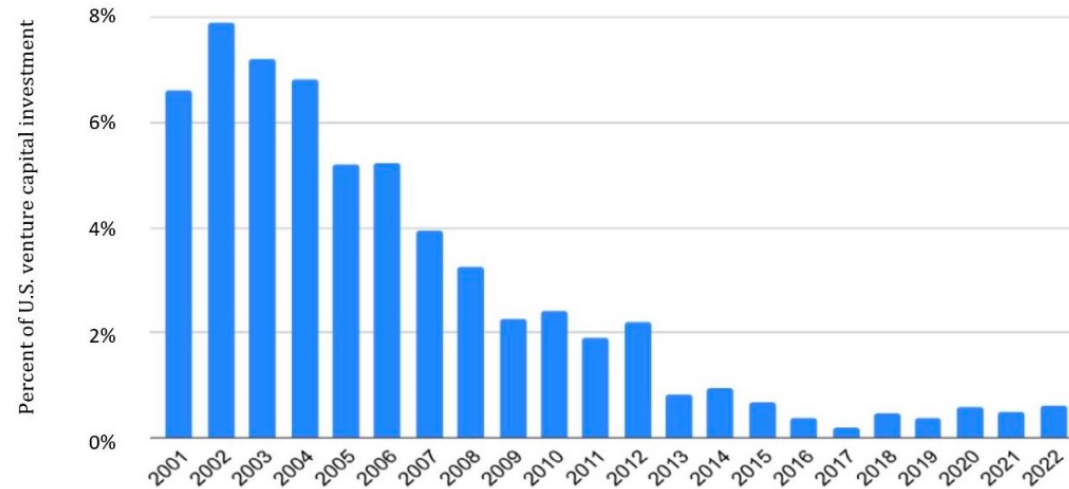
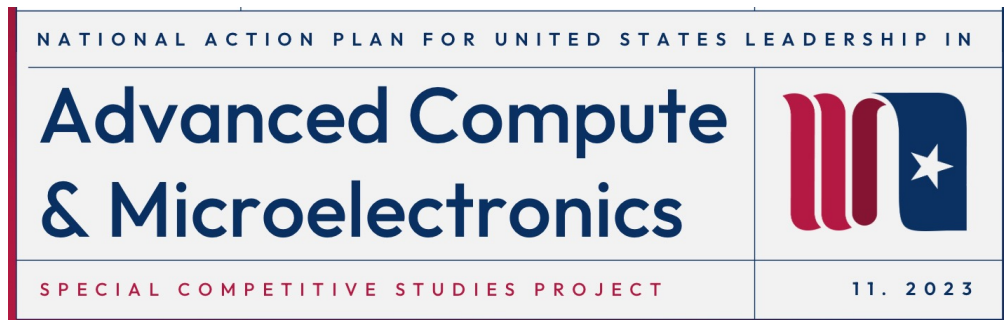


Figure 2: Percent of U.S. venture capital investment in semiconductors since 2001.
Source: Courtesy of Pear Ventures using original data retrieved from Crunchbase in August 2022.

Recommendation 6: The Secretary of Commerce should ensure that by the end of 2023, the NSTC creates an investment fund on the order of \$500 million to provide financial support and in-kind access to prototyping and tools for semiconductor startups.



2.2 Optimize the NSTC Investment Fund to Pursue Disruptive Innovation

The CHIPS & Science Act authorized the NSTC to launch an investment fund that, if implemented effectively, can provide patient capital to scale transformative innovations from across the compute stack. Entrepreneurs working on disruptive technologies in the microelectronics space face daunting challenges, including very high initial costs compared to other industries and an understandable reluctance among many venture capital (VC) firms to invest in hardware technologies with a consolidated market and an uncertain timeline to commercialization.¹⁰¹ Since bets by even the most accomplished VC funds fail far more often than they succeed, an NSTC fund demands a higher-than-typical tolerance for uncertainty and risk.¹⁰²

Objective: Launch a sufficiently resourced NSTC fund, potentially via an external partner, focused on de-risking seed and early-stage startups aiming to bring disruptive technologies from across the compute stack to market.

Method: Adopt best practices from notable deep tech investment funds, such as In-Q-Tel (IQT) and The Engine, as well as impact investing principles.¹⁰³ The fund should be shaped according to the following characteristics:

- **Focus on Seed- and Early-Stage Investments.** The most significant funding gap for disruptive technologies across the microelectronics stack exists earlier in the startup

- **\$500 Million Initial Capitalization.**¹⁰⁷ A larger fund will allow for additional shots on goal and offer additional flexibility to support scaling via larger Stage B funding rounds.
- **Capital Allocation Council.** Enabling private sector participation in the fund to provide seasoned technical expertise, evaluative discipline, and the strongest possible diligence. Select VC investors, horizon scanners, and technologists could be convened in an off-the-record, advisory fashion to support NSTC fund managers.

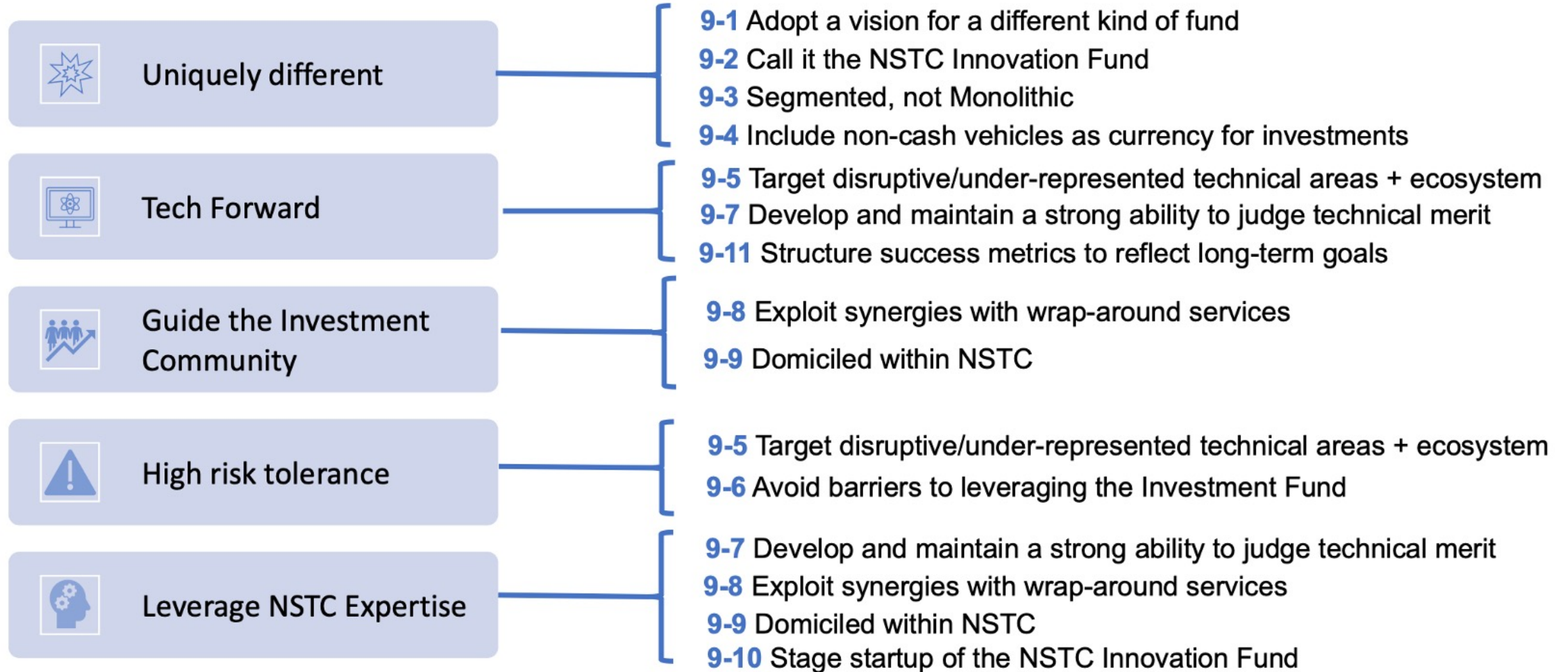
2.3 Augment the NSTC Fund with an Incubator Function

Navigating the microelectronics R&D and funding landscape can be a disorienting experience for innovators. Dozens of federal R&D programs – run seemingly in parallel and with limited connectivity – carry different requirements, grant applications, and government customers, creating hurdles that primarily impact small- and medium-size businesses. Once innovators develop a product, taking their technology to market can be an even more challenging experience. Institutionalized support is needed to increase the odds of successful commercialization.

Objective: Provide a dedicated “help desk” and commercialization support function for microelectronics researchers and innovators to lower barriers to entry.

Method: Establish an “incubator” program linked to the NSTC Investment Fund to offer commercialization support, access to cutting-edge equipment, and mentorship programs for microelectronics innovators. Dedicated commercialization support would increase the odds of success for the NSTC program and startups funded by the investment fund. Such a program should be modeled on approaches taken in recent years by established deep tech investment funds and agile government funders like IQT, DARPA, and the Defense Innovation Unit.¹⁰⁸

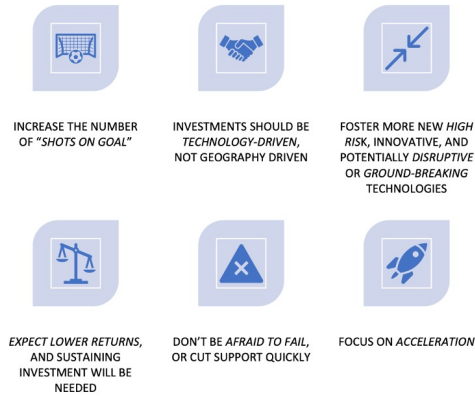
IAC Investment fund recommendations



IAC Investment fund recommendations

Recommendation 9-1

Adopt a vision for a different kind of fund

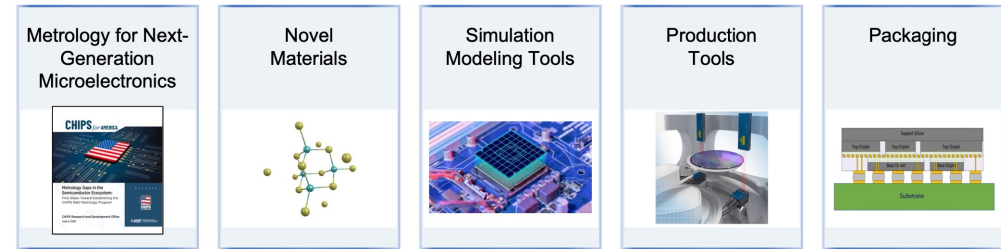


This is not a profit-driven fund, and also not an evergreen model – it will need ongoing support

- Increase the number of entrepreneurs willing to step up to hard challenges in microelectronics
- Support firms that take more risk and have a higher failure rate
- These are bets that investors who are focused on maximizing returns would not normally take; guide the investment community by de-risking and signaling
- Ventures might be in important niche areas, and have middling returns, but are strategically vital

Recommendation 9-5

Target under-represented technical areas + ecosystem



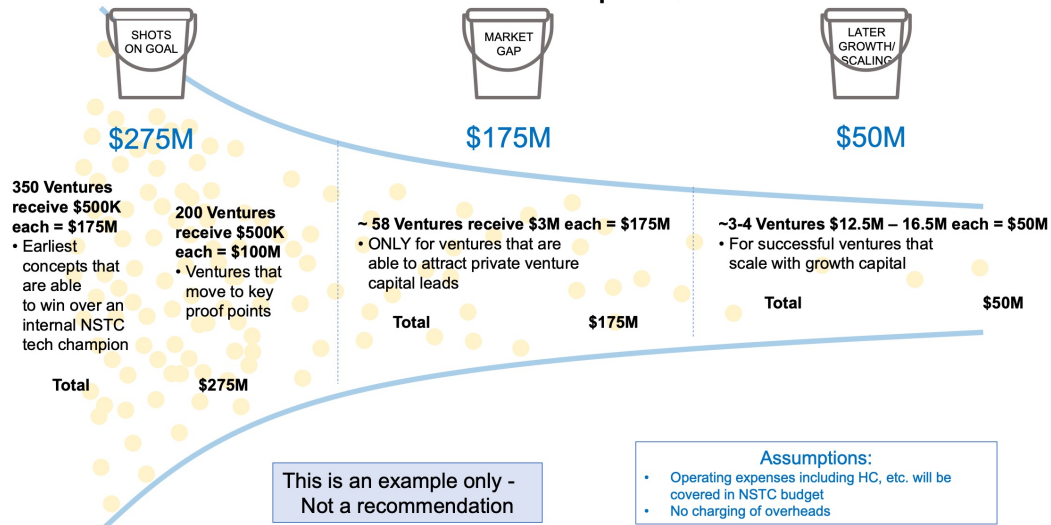
Maximize deal flow from under-represented technical areas, including those that serve economic and national security interests

The committee specifically calls for the fund to seek high-risk technical challenges that are farther out on the risk/reward frontier than traditional venture investors might be willing to fund at inception

Look at the broader ecosystem and think strategically for the long term

Critical materials, tools, metrology, address 3D scaling challenges

Notional Illustrative Example: \$500M Fund



Recommendation 9-10

Stage start-up of the Innovation Fund



May be advantageous to delay startup of the Innovation Fund until a later time, after the NSTC is up and running and has a clearer sense of where technology gaps, shortfalls, disruption opportunities or other priorities have emerged

- With time, the NSTC's infrastructure and in-kind services will take shape and impact how later investments will be structured.
- Sequencing of NSTC capabilities needs to be carefully considered; Innovation Fund is strategic but might not need to be an early priority



NSTC should engage startups early

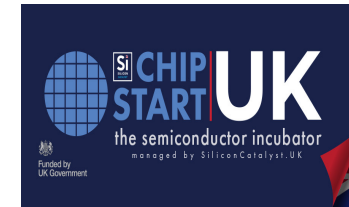
- NSTC should hire initial staff in Innovation Fund early
- Start projects, grand challenges, and other programs *immediately* to start tech development
- Convene startups and investors
- Institute mentoring
- Start-ups seeking immediate support can avail themselves of NSTC wrap-around services

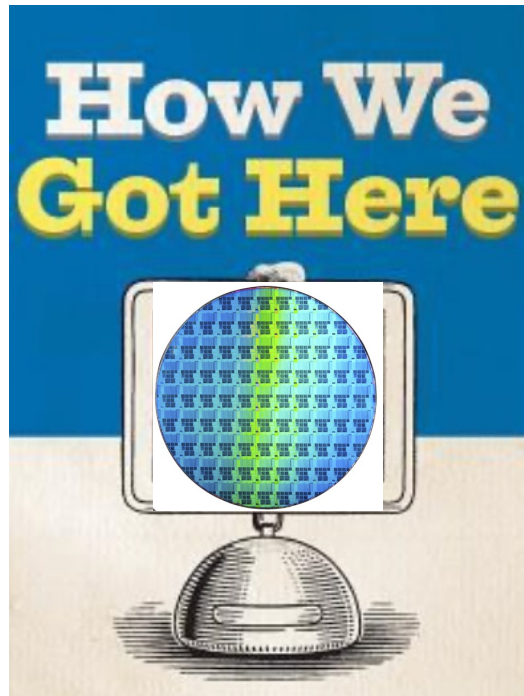
“CHIPStart UK” is an example of a fast-moving Gov’t lead initiative

- 5/23 UK semiconductor strategy published and funded at £1B
- DSIT responsible for execution
 - Intent to create an early-stage startup program
- 7/23 Silicon Catalyst UK selected to run startup incubator
- 8/23 Call for applications: 27 startups applied
- 10/23 Final selection: 11 startups admitted for 9-month program
- 2/24 Call for 2nd cohort applications
- 3/24 Demo day at UK Semiconductor conference sponsored by DSIT/GSA; 1st in over a decade

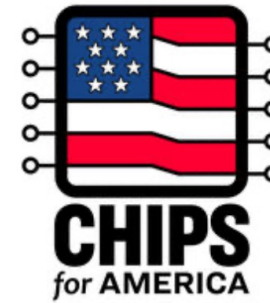


Department for
Science, Innovation
& Technology





BEHIND THE
STARTUP

A stack of US dollar bills is positioned behind the word "STARTUP".

Recommendations
Policy and
Partnerships



Recommendations

Execute what's already been authorized and appropriated with the CHIPS Act

1) Accelerate access to affordable prototyping capabilities for startups through the various CHIPS Act initiatives

- NSTC for silicon, NAPMP for packaging and Mfg. USA for digital twin
- DOD Commons (Hubs) for “lab to fab” – 8 regional Hubs launched Sept 23

2) Implement NSTC's Innovation fund at a minimum of \$0.5B consistent with the IAC and SCSP recommendations

Recommendations

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- 2) Implement NSTC's Innovation fund at a minimum of \$0.5B consistent with the IAC and SCSP recommendations

Supplement with ongoing government funding streams

- 3) Enhance existing SBIR/STTR and DIU programs with a “fast-track entrepreneur lane” to 3x funding across NSF/DOE/DARPA/DOD/NIH

- 4) Leverage ongoing government initiatives by ensuring that startup investment and procurement are included (e.g., DOD NDIS ((National Defense Industrial Strategy) and SBICCT (Small Business Investment Company Critical Technologies)), and DOE Office of Science (BES) and AMO funding and loan programs

Recommendations (Part 2)

Complement by attracting further private investment

5) Increase Corporate VC (CVC) investments by 2x to provide signals to VC for early-stage startups with innovative technologies, especially in materials, metrology, processes and EDA

6) Increase the number of “Hard Tech” and specialty fund VCs by identifying and addressing gaps in incentives and policies via a neutral technology-based organization (e.g., MITRE, SRI, COC – Council on Competitiveness)

7) Commission the OSTP to establish means of collaboration with allied nations’ CHIPS Acts and ensure coordination across government agencies on initiatives that support startups

8) Enhance capital gains provisions for entrepreneurs and investors that have long liquidity timelines (e.g., QSBS - Qualified Small Business Stock for capital gains)

Bottom line up front (BLUF)

Semiconductors are resurgent

Company valuations and profitability

- 8 of the top 20 market caps in tech
- 3rd most profitable industry

AI is profoundly hardware limited -- it's the next gold rush

Essential assets in a geopolitical sea change away from globalism

A surge of investments are underway

CHIPS Act(s) in various countries and regions

VCs are wading back in as there are green shoots in Deep Tech and specialty funds – A contrarian opportunity

Reasonable M&A and IPO opportunities for startups

Chiplets and advanced packaging can advantage startups

Semiconductor startups face daunting challenges

Escalating cost of innovation: prototyping access and costs

Sustained decline of venture capital for semiconductors

Achieving product-market fit remains challenging

Diminished customer appetite to award design wins to startups

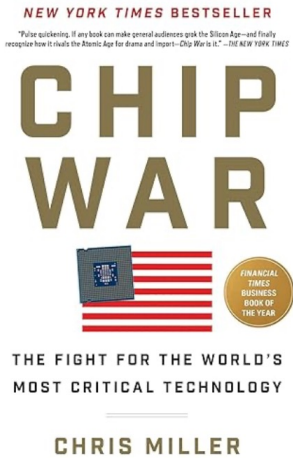
But more research will not lead to commercialization unless we continue to build the startup playbook

Aggressively implement CHIPS Act investments for prototyping and startup funds with a sense of urgency

Supplement with existing government programs and funding streams

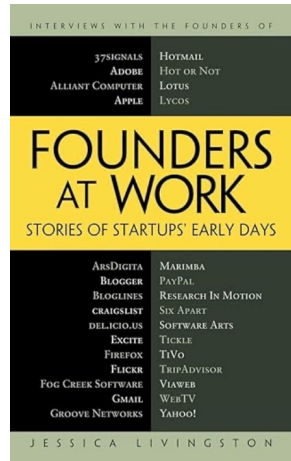
Strengthen startup ecosystem for translation to industry

Where can you learn more?



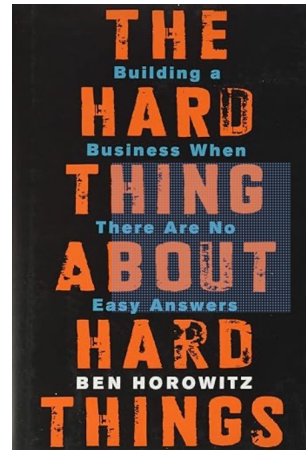
Semi History

Chris Miller



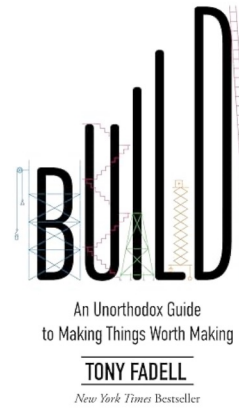
Startup stories
Internet Era

Jessica Livingston



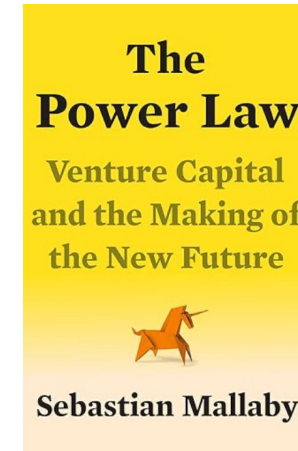
Startup stories
Cloud/SAS era

Ben Horowitz



Hardware
Startups

Tony Fadell



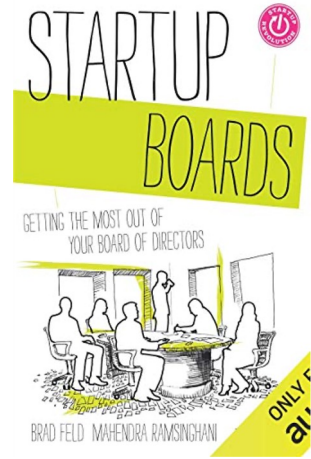
Venture Capital

Sebastian Mallaby



Funding pitchdeck
and storytelling

David Reimer



Startup Boards

Brad Feld

CHIPS Act:

- [NATCAST](#) (NSTC operator)
- [DOC/NIST](#) (CHIPS.GOV info)
- [IAC](#) (Industrial Advisory Committee)

Gov't agencies:

- [DOD OSC](#) (Office of Strategic Capital)
- [DIANA](#) (DOD Accelerator)
- [DARPA ERI](#)
- [DOE BES](#)

Thank you – Q&A

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